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## MAX22199

## Octal Industrial Digital Input

### General Description

The MAX22199 is an IEC 61131-2 compliant industrial digital input device. The MAX22199 translates eight 24V current-sinking industrial inputs to a serialized SPI-compatible output that interfaces with 3V to 5.5V logic. It can operate as eight Type 1/Type 3 digital inputs or four Type 2 digital inputs. The device provides diagnostic functions, including thermal shutdown, 24V under voltage alarm, 24V missing voltage alarm, and SPI and CRC communication error detection. All of the faults can be configured to generate an interrupt using the FAULT pin.

For robust operation in industrial environments, each input includes a programmable glitch filter. Noise filters on each channel can be independently programmed to one of eight values between 50 $\mu$ s and 20ms or filter bypass.

The MAX22199 has a 4-pin SPI interface and, in addition, uses the LATCH input for synchronizing input data sampling across multiple devices.

The MAX22199 field-side accepts a single 7V to 65V supply to the V<sub>DD24</sub> pin. When powered by the field supply, the MAX22199 generates a 3.3V output from an integrated LDO regulator, which can provide up to 25mA of current for external loads in addition to powering the MAX22199. Alternatively, the MAX22199 can be powered from a 3.0V to 5.5V logic side supply connected to the V<sub>DD</sub> pin. For flexibility, the SPI interface operates at 3.3V or 5V logic levels as controlled by the V<sub>L</sub> pin.

### Applications

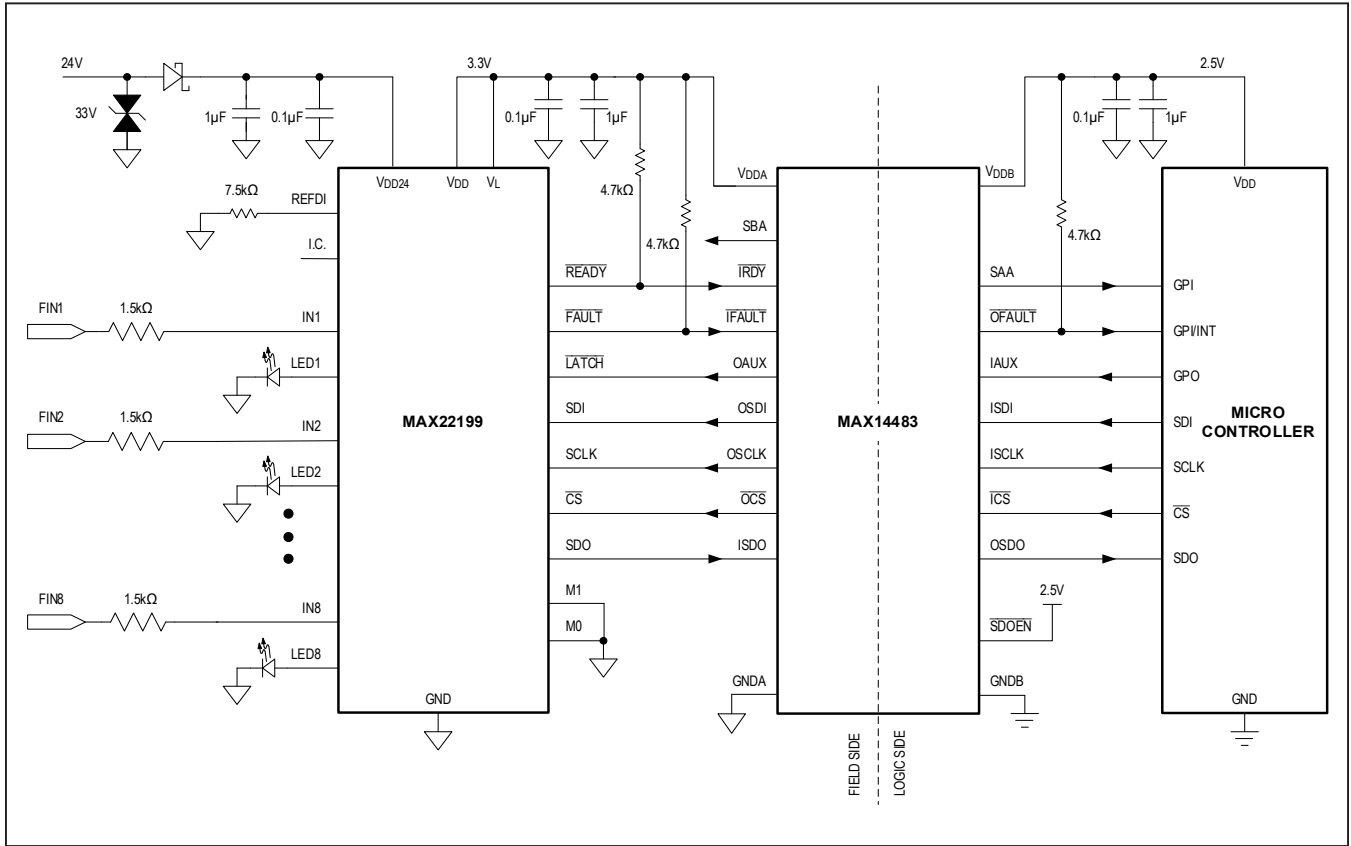
- Programmable Logic Controllers
- Distributed Control System
- Motor Control
- Building Automation

### Benefits and Features

- High Integration Reduces BOM Count and Board Space
  - Eight Input Channels with Serializer
  - Operates Directly from Field Supply (7V to 65V)
  - Compatible with 3.3V or 5V Logic
  - 5mm x 5mm TQFN Package
- Reduced Power and Heat Dissipation
  - 0.6mA (typ) Supply Current
  - $\pm 11\%$  Accurate Input-Current Limiters
  - Energyless Field-Side LED Drivers
  - Low Power Dissipation with Negative Input Voltage
- Fault Tolerant
  - Input Protection to  $\pm 40V$
  - Integrated Field-Supply Voltage Monitors
  - 5-Bit CRC SPI Error Detection
- Configurability Enables Wide Range of Applications
  - Configurable Input Current from 0.5mA to 3.4mA
  - Selectable Input Debounce Filtering
  - Current Sources Can Be Disabled
  - Supports Daisy-Chain SPI and Direct SPI
- Robust Design
  - $\pm 8kV$  Contact ESD and  $\pm 15kV$  Air-Gap ESD Using Minimum 1k $\Omega$  Resistor
  - $\pm 2kV$  Surge Tolerant Using Minimum 1k $\Omega$  Resistor
  - $-40^{\circ}C$  to  $+125^{\circ}C$  Ambient Operating Temperature
- Advanced Diagnostics Can Be Provided by [MAX22190](#)
  - Pin-to-Pin Compatible
  - Register Compatible

[Ordering Information](#) appears at end of data sheet.

Isolated Octal Type 1/3 Digital Input



### Absolute Maximum Ratings

|  |                                     |  |
|--|-------------------------------------|--|
| $V_L, V_{DD}$ to GND .....                             | -0.3V to +6V                        | Continuous Power Dissipation ( $T_A = +70^\circ\text{C}$ ) |
| $V_{DD24}$ to GND .....                                | -0.3V to +70V                       | TQFN (derate at 27.8mW/°C above +70°C) .....               |
| SCLK, $\overline{\text{CS}}$ , SDI, M0, M1 to GND..... | -0.3V to +6V                        | 2222mW   |
| LATCH, FAULT, READY to GND .....                       | -0.3V to +6V                        | Operating Temperature Range                                |
| REFDI to GND.....                                      | -0.3V to ( $V_{DD} + 0.3\text{V}$ ) | Ambient Temperature .....                                  |
| SDO to GND.....  | -0.3V to ( $V_L + 0.3\text{V}$ )    | +125°C   |
| IN1–IN8 to GND .....                                   | -40V to +40V                        | Junction Temperature .....                                 |
| LED1–LED8 to GND .....                                 | -0.3V to +6V                        | +150°C   |
|  |                                     | Storage Temperature Range .....                            |
|  |                                     | -65°C to +150°C  |
|  |                                     | Lead Temperature (soldering, 10s) .....                    |
|  |                                     | +300°C   |
|  |                                     | Soldering (reflow) .....                                   |
|  |                                     | +260°C   |

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

### Package Information

|   |                         |
|---|-------------------------|
| <b>32 TQFN</b>                              |                         |
| Package Code                                | T3255+6                 |
| Outline Number                              | <a href="#">21-0140</a> |
| Land Pattern Number                         | <a href="#">90-0603</a> |
| <b>THERMAL RESISTANCE, MULTILAYER BOARD</b> |                         |
| Junction to Ambient ( $\theta_{JA}$ )       | 36°C/W                  |
| Junction to Case ( $\theta_{JC}$ )          | 3°C/W                   |

Package thermal resistances were obtained using the method described in JEDEC specification JESD51-7, using a four-layer board. For detailed information on package thermal considerations, refer to [www.maximintegrated.com/thermal-tutorial](http://www.maximintegrated.com/thermal-tutorial).

For the latest package outline information and land patterns (footprints), go to [www.maximintegrated.com/packages](http://www.maximintegrated.com/packages). Note that a "+", "#", or "-" in the package code indicates RoHS status only. Package drawings may show a different suffix character, but the drawing pertains to the package regardless of RoHS status.

### DC Electrical Characteristics

$V_L - V_{GND} = +3.0\text{V}$  to  $+5.5\text{V}$ ,  $V_{DD} - V_{GND} = +3.0\text{V}$  to  $+5.5\text{V}$ ,  $T_A = -40^\circ\text{C}$  to  $+125^\circ\text{C}$ ,  $C_L = 15\text{pF}$ , unless otherwise noted. Typical values are at  $V_L - V_{GND} = +3.3\text{V}$ ,  $V_{DD} - V_{GND} = +3.3\text{V}$ ,  $V_{DD24} - V_{GND} = +24\text{V}$ ,  $V_{IN\_} = +24\text{V}$ , and  $T_A = +25^\circ\text{C}$ . (Note 1)

| PARAMETER                            | SYMBOL     | CONDITIONS                      |  | MIN | TYP | MAX | UNITS |
|--------------------------------------|------------|---------------------------------|--|-----|-----|-----|-------|
| <b>POWER SUPPLIES</b>                |            |                                 |  |     |     |     |       |
| Logic Supply Voltage                 | $V_L$      |                                 |  | 3.0 |     | 5.5 | V     |
| Logic Supply Current                 | $I_L$      | $V_L = 5.5\text{V}$             | $\overline{\text{CS}} = V_L$ ,<br>All logic pins static  |     | 13  | 30  | μA    |
| Supply Voltage                       | $V_{DD24}$ | Normal operation                |  | 7   |     | 65  | V     |
|                                      | $V_{DD}$   | Powered from an external supply |  | 3.0 |     | 5.5 | V     |
| Supply Current of $V_{DD24}$         | $I_{DD24}$ | $V_{DD24} = 24\text{V}$         | IN1–IN8 = 0V, LED1–LED8 = GND, SPI static, REFDI = 7.5kΩ |     | 0.6 | 1.2 | mA    |
| Supply Current Powered From $V_{DD}$ | $I_{DD}$   | $V_{DD} = 3.3\text{V}$          | IN1–IN8 = 0V, LED1–LED8 = GND, SPI static, REFDI = 7.5kΩ |     | 0.6 | 1.2 | mA    |

### DC Electrical Characteristics (continued)

$V_L - V_{GND} = +3.0V$  to  $+5.5V$ ,  $V_{DD} - V_{GND} = +3.0V$  to  $+5.5V$ ,  $T_A = -40^\circ C$  to  $+125^\circ C$ ,  $C_L = 15pF$ , unless otherwise noted. Typical values are at  $V_L - V_{GND} = +3.3V$ ,  $V_{DD} - V_{GND} = +3.3V$ ,  $V_{DD24} - V_{GND} = +24V$ ,  $V_{IN\_} = +24V$ , and  $T_A = +25^\circ C$ . (Note 1)

| PARAMETER  | SYMBOL                     | CONDITIONS                                      | MIN  | TYP  | MAX  | UNITS      |
|--|----------------------------|---|------|------|------|------------|
| $V_{DD}$ Undervoltage-Lockout Threshold              | $V_{UVLO}$                 | $V_{DD}$ rising                                 | 2.4  |      | 2.9  | V          |
| $V_{DD}$ Undervoltage-Lockout Threshold Hysteresis   | $V_{UVHYST}$               |   |      | 0.07 |      | V          |
| $V_{DD24}$ Undervoltage-Lockout Threshold            | $V_{UVLO24}$               | $V_{DD24}$ rising                               | 6    |      | 6.8  | V          |
| $V_{DD24}$ Undervoltage-Lockout Threshold Hysteresis | $V_{UVHYST24}$             |   |      | 0.5  |      | V          |
| $V_L$ Undervoltage-Lockout Threshold                 | $V_{UVLOVL}$               | $V_L$ rising                                    | 0.9  |      | 1.6  | V          |
| $V_L$ Undervoltage-Lockout Threshold Hysteresis      | $V_{UVHYSTVL}$             |   |      | 0.07 |      | V          |
| Regulator Output Voltage                             | $V_{DD}$                   | $I_{LOAD} = 1mA$ , $V_{DD24} \geq 7V$           | 3.0  | 3.3  | 3.6  | V          |
| Line Regulation                                      | $dV_{DDLIN}$               | $I_{LOAD} = 1mA$ , $V_{DD24} = 12V$ to $24V$    |      | 0    |      | mV         |
| Load Regulation                                      | $dV_{DDLLOAD}$             | $I_{LOAD} = 1mA$ to $10mA$ , $V_{DD24} = 24V$   |      | 4    |      | mV         |
| Regulator Current Capability                         | $I_{DD\_CC}$               |   |      |      | 25   | mA         |
| Short-Circuit Current                                | $I_{DD24\_SC}$             | $V_{DD24}$ current when $V_{DD}$ shorted to GND | 28   |      | 50   | mA         |
| $\overline{READY}$ Threshold                         | $V_{READY}$                | $V_{DD}$ rising, $V_{DD24} = 0V$                | 2.4  |      | 2.9  | V          |
| $\overline{READY}$ Threshold Hysteresis              | $V_{READY\_HYST}$          |   |      | 0.07 |      | V          |
| $\overline{READY}$ Delay                             | $\overline{READY}_{DELAY}$ | $V_{DD}$ valid to $\overline{READY}$ low        |      | 1    |      | ms         |
| <b>SUPPLY ALARMS</b>                                 |                            |   |      |      |      |            |
| $V_{DD24}$ UV Alarm On/Off                           | $V_{ALRMOFFUV}$            | $V_{DD24}$ rising, under voltage                |      |      | 17   | V          |
| $V_{DD24}$ UV Alarm Off/On                           | $V_{ALRMONUV}$             | $V_{DD24}$ falling, under voltage               | 15   |      |      | V          |
| Glitch Filter for $V_{DD24}$ UV                      |                            |   |      | 3    |      | $\mu s$    |
| $V_{DD24}$ VM Alarm On/Off                           | $V_{ALRMOFFVM}$            | $V_{DD24}$ rising, missing voltage              |      |      | 13.9 | V          |
| $V_{DD24}$ VM Alarm Off/On                           | $V_{ALRMONVM}$             | $V_{DD24}$ falling, missing voltage             | 12.1 |      |      | V          |
| Glitch Filter for $V_{DD24}$ VM                      |                            |   |      | 3    |      | $\mu s$    |
| <b>TEMPERATURE ALARM</b>                             |                            |   |      |      |      |            |
| Thermal-Shutdown Threshold                           | $T_{SHDN}$                 | OTSHDN bit set in FAULT2 register               |      | 165  |      | $^\circ C$ |
| Thermal-Shutdown Hysteresis                          | $T_{SHDN\_HYS}$            |   |      | 10   |      | $^\circ C$ |
| <b>IN_ INPUTS</b>                                    |                            |   |      |      |      |            |
| Input Threshold Low-to-High                          | $V_{THIN+}$                | All inputs, IN1 to IN8                          |      |      | 6    | V          |
| Input Threshold High-to-Low                          | $V_{THIN-}$                | All inputs, IN1 to IN8                          | 4.4  |      |      | V          |
| Input Threshold Hysteresis                           | $V_{INHYST}$               | All inputs, IN1 to IN8                          |      | 0.8  |      | V          |

## DC Electrical Characteristics (continued)

$V_L - V_{GND} = +3.0V$  to  $+5.5V$ ,  $V_{DD} - V_{GND} = +3.0V$  to  $+5.5V$ ,  $T_A = -40^\circ C$  to  $+125^\circ C$ ,  $C_L = 15pF$ , unless otherwise noted. Typical values are at  $V_L - V_{GND} = +3.3V$ ,  $V_{DD} - V_{GND} = +3.3V$ ,  $V_{DD24} - V_{GND} = +24V$ ,  $V_{IN\_} = +24V$ , and  $T_A = +25^\circ C$ . (Note 1)

| PARAMETER  | SYMBOL         | CONDITIONS   |                          | MIN  | TYP  | MAX  | UNITS   |
|--|----------------|--|--------------------------|------|------|------|---------|
| DI Leakage   | $I_{DI\_LEAK}$ | Channel disabled,<br>$EN\_ = 0$  | IN1 to IN8 = 36V         |      | 73   |      | $\mu A$ |
|  |                |  | IN1 to IN8 = 24V         |      | 42   |      | $\mu A$ |
| <b>LED_ OUTPUTS</b>  |                |  |                          |      |      |      |         |
| LED On-State Current   | $I_{LEDON}$    | $R_{REFDI} = 7.5k\Omega$ , $V_{LED} = 3V$                                      |                          | 1.5  |      |      | mA      |
| <b>REFDI</b>   |                |  |                          |      |      |      |         |
| REFDI Pin Voltage  | $V_{REFDI}$    | $R_{REFDI} = 5.2k\Omega$ to $36k\Omega$  |                          |      | 0.61 |      | V       |
| <b>IN_ INPUT CURRENT</b>   |                |  |                          |      |      |      |         |
| Input Current Limit  | $I_{INLIM}$    | $28V > V_{IN\_} > 5V$  | $R_{REFDI} = 7.5k\Omega$ | 2.10 | 2.35 | 2.60 | mA      |
|  |                |  | $R_{REFDI} = 5.2k\Omega$ | 3.05 | 3.39 | 3.71 |         |
| <b>FIELD INPUT TYPE 1, 3: EXTERNAL SERIES RESISTOR <math>R_{IN\_} = 1.5k\Omega</math>, <math>R_{REFDI} = 7.5k\Omega</math></b> |                |  |                          |      |      |      |         |
| Field Input Threshold Low-to-High  | $V_{THFIN+}$   | $R_{REFDI} = 7.5k\Omega$ ,<br>external series resistor $R_{IN\_} = 1.5k\Omega$ |                          |      |      | 9.9  | V       |
| Field Input Threshold High-to-Low  | $V_{THFIN-}$   | $R_{REFDI} = 7.5k\Omega$ ,<br>external series resistor $R_{IN\_} = 1.5k\Omega$ |                          | 7.4  |      |      | V       |
| Field Input Threshold Hysteresis   | $V_{FINHYST}$  | $R_{REFDI} = 7.5k\Omega$ ,<br>external series resistor $R_{IN\_} = 1.5k\Omega$ |                          |      | 0.9  |      | V       |
| <b>FIELD INPUT TYPE 2: EXTERNAL SERIES RESISTOR <math>R_{IN\_} = 1k\Omega</math>, <math>R_{REFDI} = 5.2k\Omega</math></b>      |                |  |                          |      |      |      |         |
| Field Input Threshold Low-to-High  | $V_{THFIN+}$   | $R_{REFDI} = 5.2k\Omega$ ,<br>external series resistor $R_{IN\_} = 1k\Omega$   |                          |      |      | 9.9  | V       |
| Field Input Threshold High-to-Low  | $V_{THFIN-}$   | $R_{REFDI} = 5.2k\Omega$ ,<br>external series resistor $R_{IN\_} = 1k\Omega$   |                          | 7.4  |      |      | V       |
| Field Input Threshold Hysteresis   | $V_{FINHYST}$  | $R_{REFDI} = 5.2k\Omega$ ,<br>external series resistor $R_{IN\_} = 1k\Omega$   |                          |      | 0.9  |      | V       |
| <b>INPUT FILTER</b>  |                |  |                          |      |      |      |         |
| Input Filter Delay<br>(See bits $DELAY\_ [2:0]$ in $FLT\_$ register)   | $t_{BOUNCE}$   | FBP_ = 1: bypass filtering   |                          |      | 2    |      | $\mu s$ |
|  |                | FBP_ = 0, DELAY_ = 0   |                          |      | 0.05 |      | ms      |
|  |                | FBP_ = 0, DELAY_ = 1   |                          |      | 0.1  |      |         |
|  |                | FBP_ = 0, DELAY_ = 2   |                          |      | 0.4  |      |         |
|  |                | FBP_ = 0, DELAY_ = 3   |                          |      | 0.8  |      |         |
|  |                | FBP_ = 0, DELAY_ = 4   |                          |      | 1.6  |      |         |
|  |                | FBP_ = 0, DELAY_ = 5   |                          |      | 3.2  |      |         |
|  |                | FBP_ = 0, DELAY_ = 6   |                          |      | 12.8 |      |         |
|  |                | FBP_ = 0, DELAY_ = 7   |                          |      | 20   |      |         |

**DC Electrical Characteristics (continued)**

$V_L - V_{GND} = +3.0V$  to  $+5.5V$ ,  $V_{DD} - V_{GND} = +3.0V$  to  $+5.5V$ ,  $T_A = -40^\circ C$  to  $+125^\circ C$ ,  $C_L = 15pF$ , unless otherwise noted. Typical values are at  $V_L - V_{GND} = +3.3V$ ,  $V_{DD} - V_{GND} = +3.3V$ ,  $V_{DD24} - V_{GND} = +24V$ ,  $V_{IN\_} = +24V$ , and  $T_A = +25^\circ C$ . (Note 1)

| PARAMETER   | SYMBOL                     | CONDITIONS  | MIN              | TYP  | MAX              | UNITS      |
|---|----------------------------|---|------------------|------|------------------|------------|
| <b>DYNAMIC CHARACTERISTICS</b>                                  |                            |   |                  |      |                  |            |
| Input (IN_) Sampling Rate                                       | $f_{IN}$                   | Input Filter Bypass mode  |                  | 1000 |                  | kHz        |
|   |                            | Input Filter Non-Bypass mode  |                  | 200  |                  |            |
| Minimum Detectable IN_ Pulse Width                              | $t_{PW}$                   | No external capacitors on input pins IN1 to IN8                               |                  | 3    |                  | $\mu s$    |
| $\overline{LATCH}$ Delay  |                            | Assertion of $\overline{LATCH}$ or $\overline{CS}$ until input data is frozen |                  | 50   |                  | ns         |
| $\overline{FAULT}$ Minimum Pulse Width                          | $t_{\overline{FAULT\_PW}}$ | $\overline{FAULT}$ low, pullup 4mA  | 0.8              |      |                  | $\mu s$    |
| <b>LOGIC INTERFACE</b>  |                            |   |                  |      |                  |            |
| Input Logic-High Voltage  | $V_{IH}$                   | SCLK, $\overline{CS}$ , SDI, $\overline{LATCH}$ , M0, M1 relative to GND      | $0.7 \times V_L$ |      |                  | V          |
| Input Logic-Low Voltage   | $V_{IL}$                   | SCLK, $\overline{CS}$ , SDI, $\overline{LATCH}$ , M0, M1 relative to GND      |                  |      | $0.3 \times V_L$ | V          |
| Output Logic-High Voltage                                       | $V_{OH}$                   | SDO, sourcing 4mA   | $V_L - 0.4$      |      |                  | V          |
| Output Logic-Low Voltage  | $V_{OL}$                   | SDO, $\overline{FAULT}$ , $\overline{READY}$ sinking 4mA                      |                  |      | 0.4              | V          |
| Input Pullup Resistance<br>$\overline{CS}$ , $\overline{LATCH}$ | $R_{PU}$                   |   |                  | 195  |                  | k $\Omega$ |
| Input Pulldown Resistance<br>SCLK, SDI, M1, M0                  | $R_{PD}$                   |   |                  | 195  |                  |            |

### Dynamic Electrical Characteristics

$V_L - V_{GND} = +3.0V$  to  $+5.5V$ ,  $V_{DD} - V_{GND} = +3.0V$  to  $+5.5V$ ,  $T_A = -40^\circ C$  to  $+125^\circ C$ ,  $C_L = 15pF$ , unless otherwise noted. Typical values are at  $V_L - V_{GND} = +3.3V$ ,  $V_{DD} - V_{GND} = +3.3V$ ,  $V_{DD24} - V_{GND} = +24V$ ,  $V_{IN\_} = +24V$ , and  $T_A = +25^\circ C$ . (Note 2)

| PARAMETER                                | SYMBOL              | CONDITIONS   | MIN | TYP | MAX | UNITS |
|--|---------------------|--|-----|-----|-----|-------|
| <b>SPI CHARACTERISTICS</b>               |                     |  |     |     |     |       |
| SCLK Pulse Width-High                    | $t_{SCLKH}$         | See <a href="#">Figure 1</a>   | 20  |     |     | ns    |
| SCLK Pulse Width-Low                     | $t_{SCLKL}$         | See <a href="#">Figure 1</a>   | 20  |     |     | ns    |
| SCLK Clock Period                        | $t_{SCLK}$          | See <a href="#">Figure 1</a>   | 100 |     |     | ns    |
| SCLK Clock Frequency                     | $f_{SCLK}$          |  |     |     | 10  | MHz   |
| $\overline{CS}$ Pulse Width              | $t_{CSBPW}$         | See <a href="#">Figure 1</a>   | 20  |     |     | ns    |
| SDI-to-SCLK Setup Time                   | $t_{DINSU}$         | See <a href="#">Figure 1</a>   | 5   |     |     | ns    |
| SDI-to-SCLK Hold Time                    | $t_{DINH}$          | See <a href="#">Figure 1</a>   | 15  |     |     | ns    |
| $\overline{CS}$ -Fall-to-SCLK-Rise Time  | $t_{CLK\_SU}$       | See <a href="#">Figure 1</a>   | 80  |     |     | ns    |
| SCLK-Rise-to- $\overline{CS}$ -Rise Time | $t_{CSBH}$          | Rising edge of SCLK to rising edge of $\overline{CS}$ ( <a href="#">Figure 1</a> ) | 40  |     |     | ns    |
| SDO Enable Time                          | $t_{CSB\_SDOVALID}$ | $\overline{CS}$ falling to SDO valid ( <a href="#">Figure 1</a> )                  |     |     | 50  | ns    |
| SDO Disable Time                         | $t_{CSB\_SDOTRI}$   | $\overline{CS}$ rising to SDO tristate ( <a href="#">Figure 1</a> )                |     |     | 50  | ns    |
| Output Data Propagation Delay            | $t_{DO}$            | SCLK falling edge-to-SDO valid ( <a href="#">Figure 1</a> )                        |     |     | 50  | ns    |
| Rise/Fall Time SDO                       | $t_{R/F}$           | SDO 10% to 90% rising, 90% to 10% falling  |     | 4   |     | ns    |

**Note 1:** All specifications are production tested at  $T_A = 25^\circ C$ . Specifications over temperature are guaranteed by design.

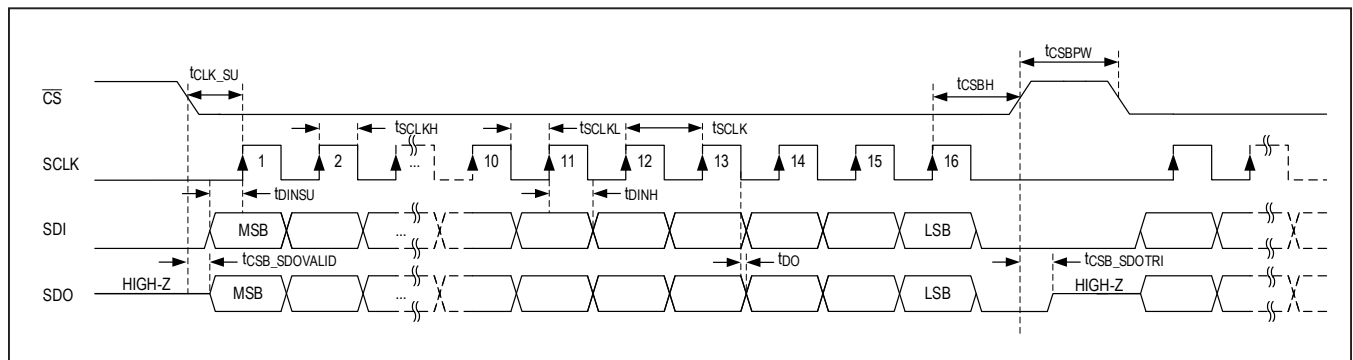


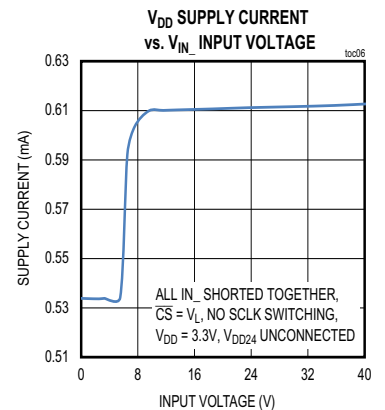
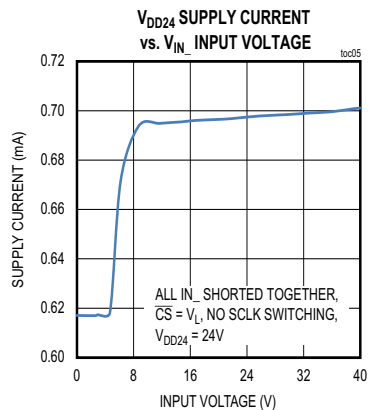
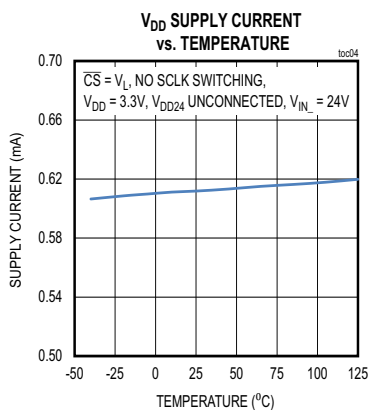
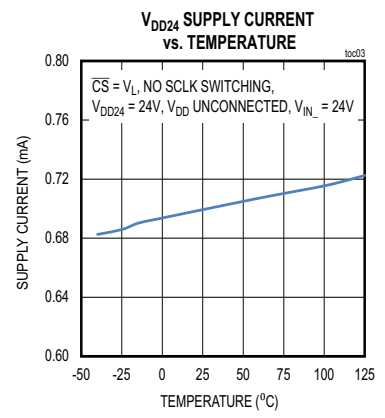
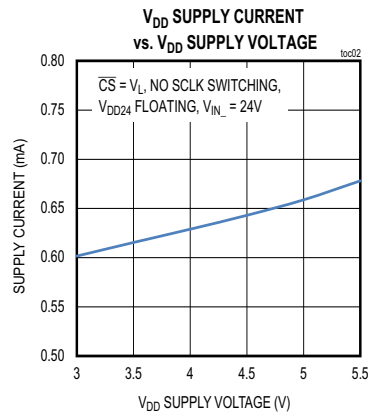
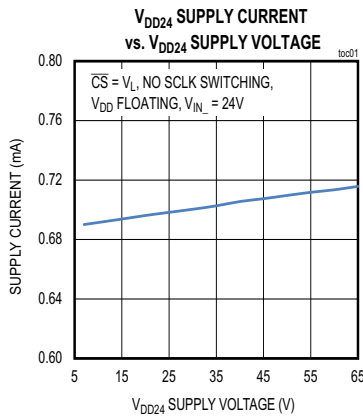
Figure 1. SPI Timing Diagram

### ESD and EMC Characteristics

| PARAMETER | SYMBOL           | CONDITIONS   | VALUE | UNITS |
|-----------|------------------|--|-------|-------|
| Surge     | Line-to-Line     | IEC 61000-4-5, 1.2/50µs pulse, minimum 1kΩ resistor in series with IN1–IN8 | ±2    | kV    |
|           | Line-to-Ground   | IEC 61000-4-5, 1.2/50µs pulse, minimum 1kΩ resistor in series with IN1–IN8 | ±2    |       |
| ESD       | Human Body Model | All pins   | ±2    |       |
|           | Contact          | IEC 61000-4-2, minimum 1kΩ resistor in series with IN1–IN8                 | ±8    |       |
|           | Air-Gap          | IEC 61000-4-2, minimum 1kΩ resistor in series with IN1–IN8                 | ±15   |       |

### Typical Operating Characteristics

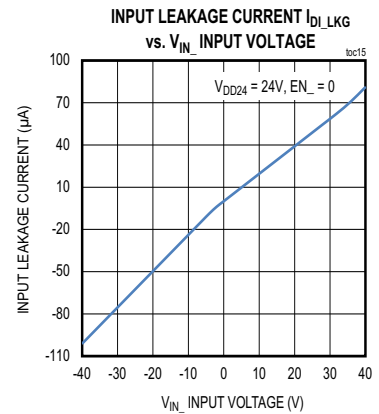
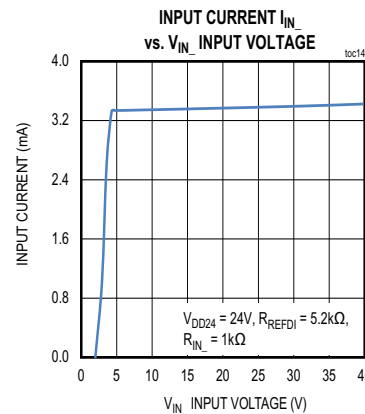
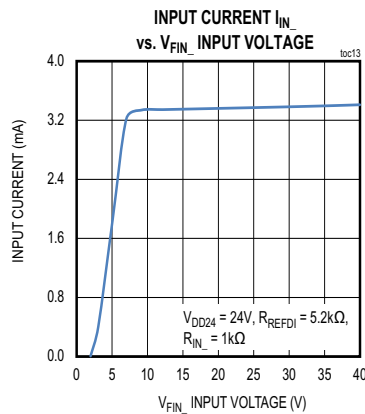
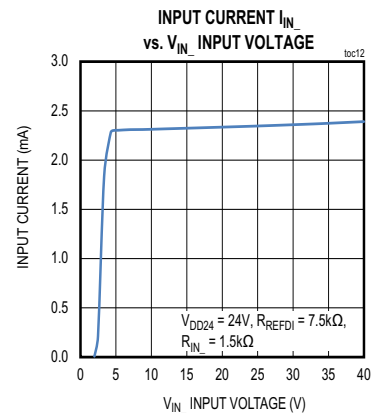
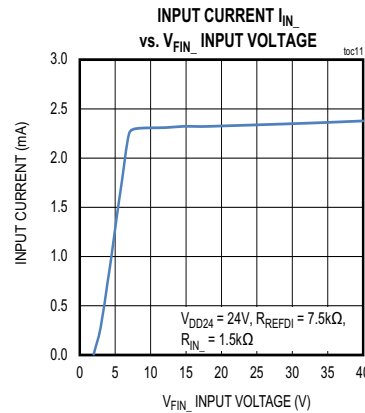
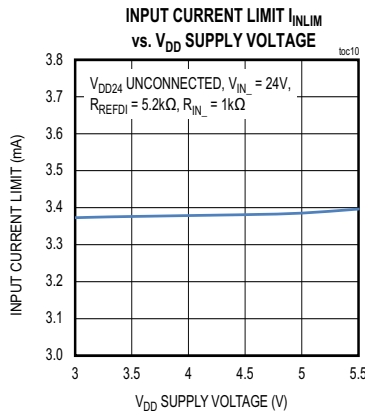
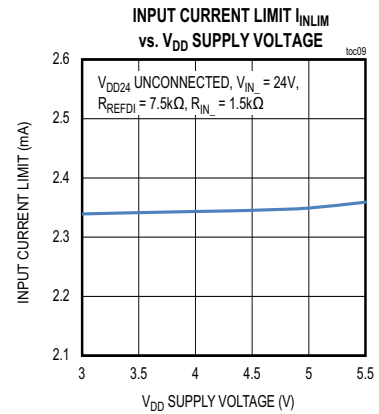
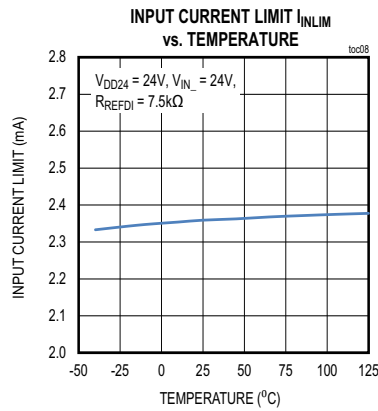
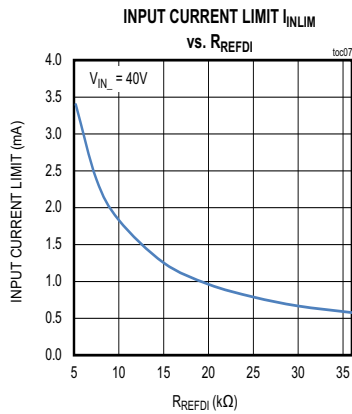
( $V_{DD24} = 24V$ ,  $V_{DD} = V_L = 3.3V$ ,  $T_A = +25^\circ C$ ,  $R_{REFDI} = 7.5k\Omega$ ,  $R_{IN} = 1.5k\Omega$ ,  $EN_ = 1$ ,  $V_{FIN_}$  = voltage measured at the field side,  $V_{IN_}$  = voltage measured at the pin, unless otherwise noted.)





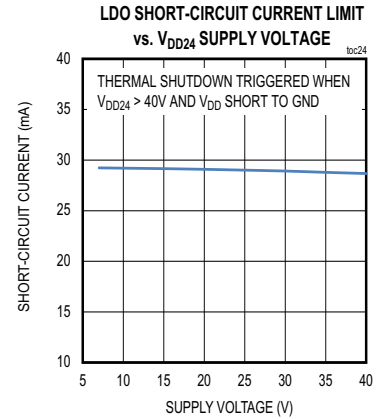
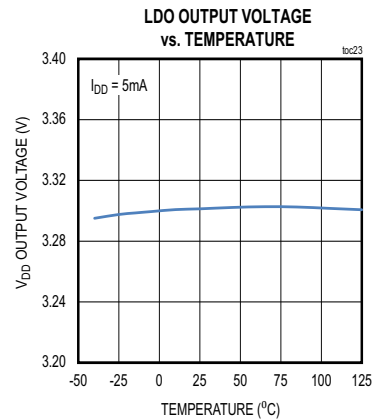
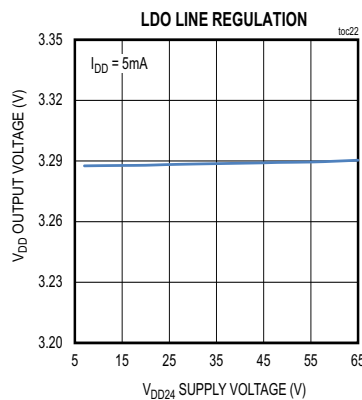
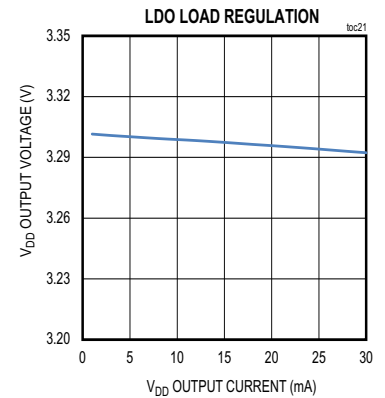
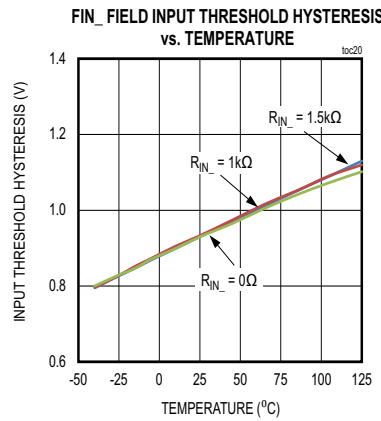
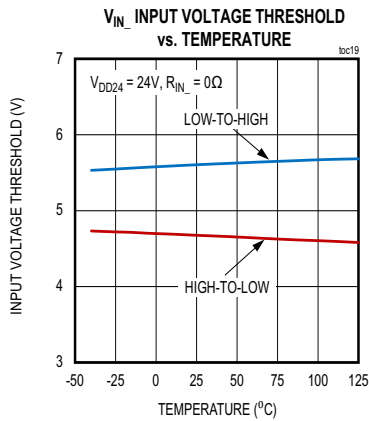
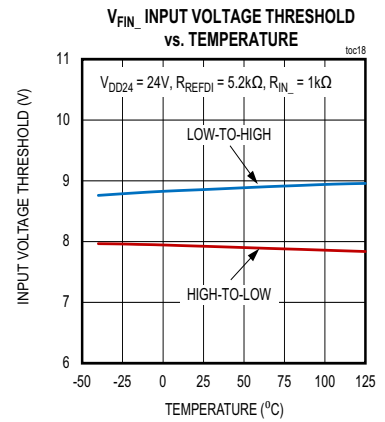
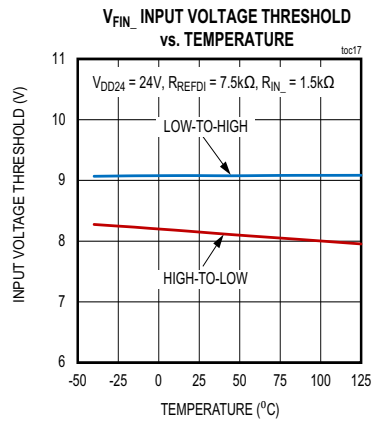
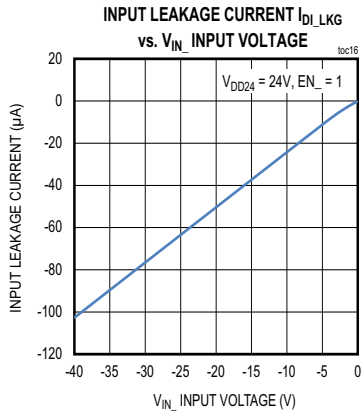
Typical Operating Characteristics (continued)

( $V_{DD24} = 24V$ ,  $V_{DD} = V_L = 3.3V$ ,  $T_A = +25^\circ C$ ,  $R_{REFDI} = 7.5k\Omega$ ,  $R_{IN} = 1.5k\Omega$ ,  $EN\_ = 1$ ,  $V_{FIN\_}$  = voltage measured at the field side,  $V_{IN\_}$  = voltage measured at the pin, unless otherwise noted.)



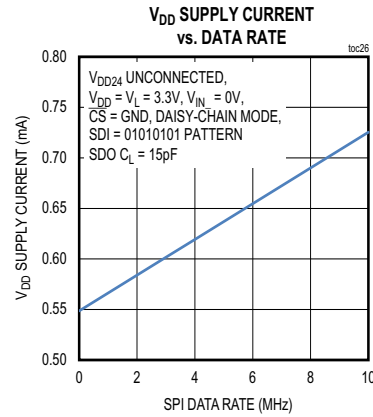
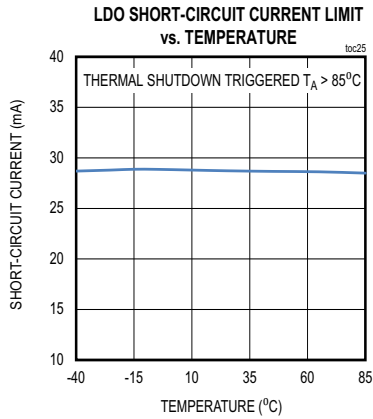
Typical Operating Characteristics (continued)

( $V_{DD24} = 24V$ ,  $V_{DD} = V_L = 3.3V$ ,  $T_A = +25^\circ C$ ,  $R_{REFDI} = 7.5k\Omega$ ,  $R_{IN} = 1.5k\Omega$ ,  $EN_ = 1$ ,  $V_{FIN_}$  = voltage measured at the field side,  $V_{IN_}$  = voltage measured at the pin, unless otherwise noted.)

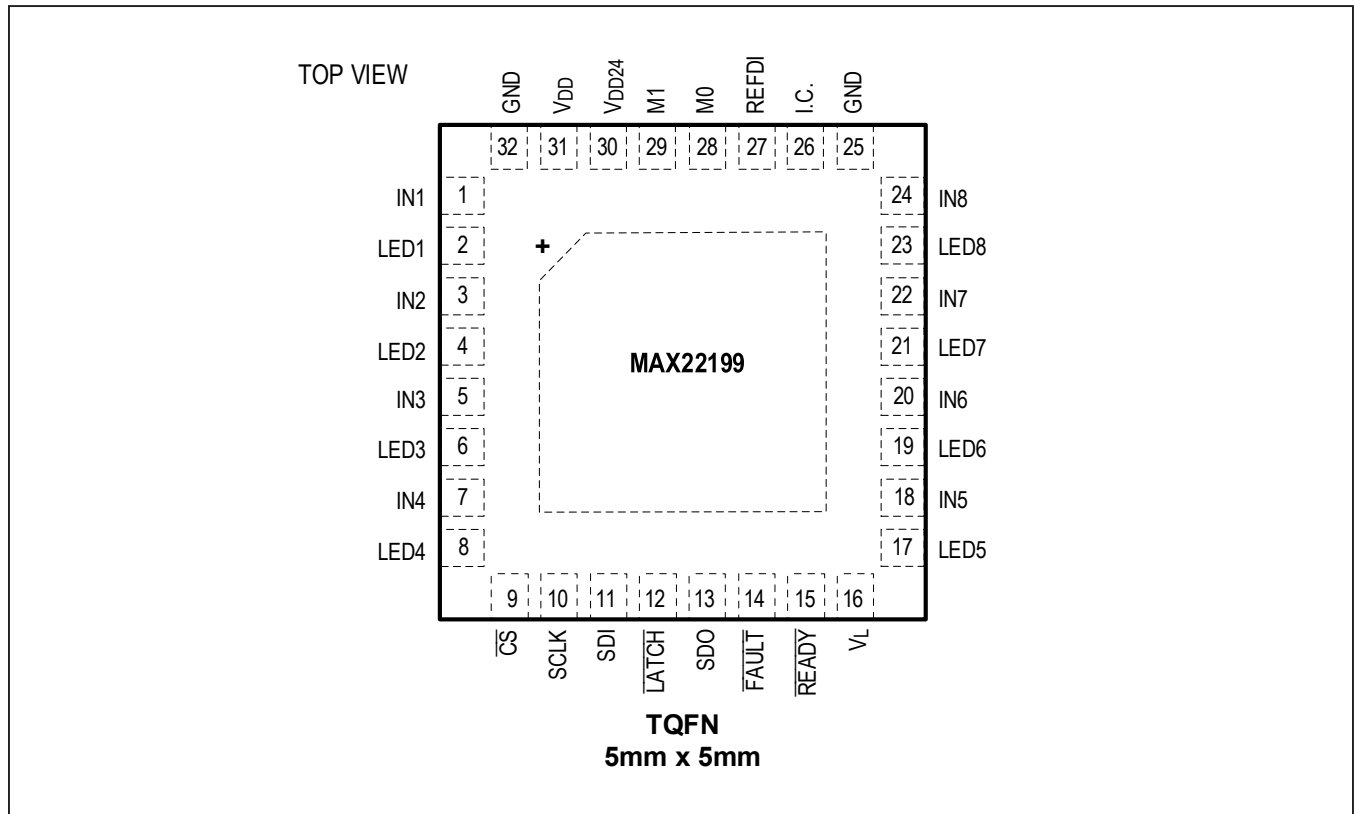


**Typical Operating Characteristics (continued)**

( $V_{DD24} = 24V$ ,  $V_{DD} = V_L = 3.3V$ ,  $T_A = +25^\circ C$ ,  $R_{REFDI} = 7.5k\Omega$ ,  $R_{IN} = 1.5k\Omega$ ,  $EN_+ = 1$ ,  $V_{FIN_+}$  = voltage measured at the field side,  $V_{IN_+}$  = voltage measured at the pin, unless otherwise noted.)



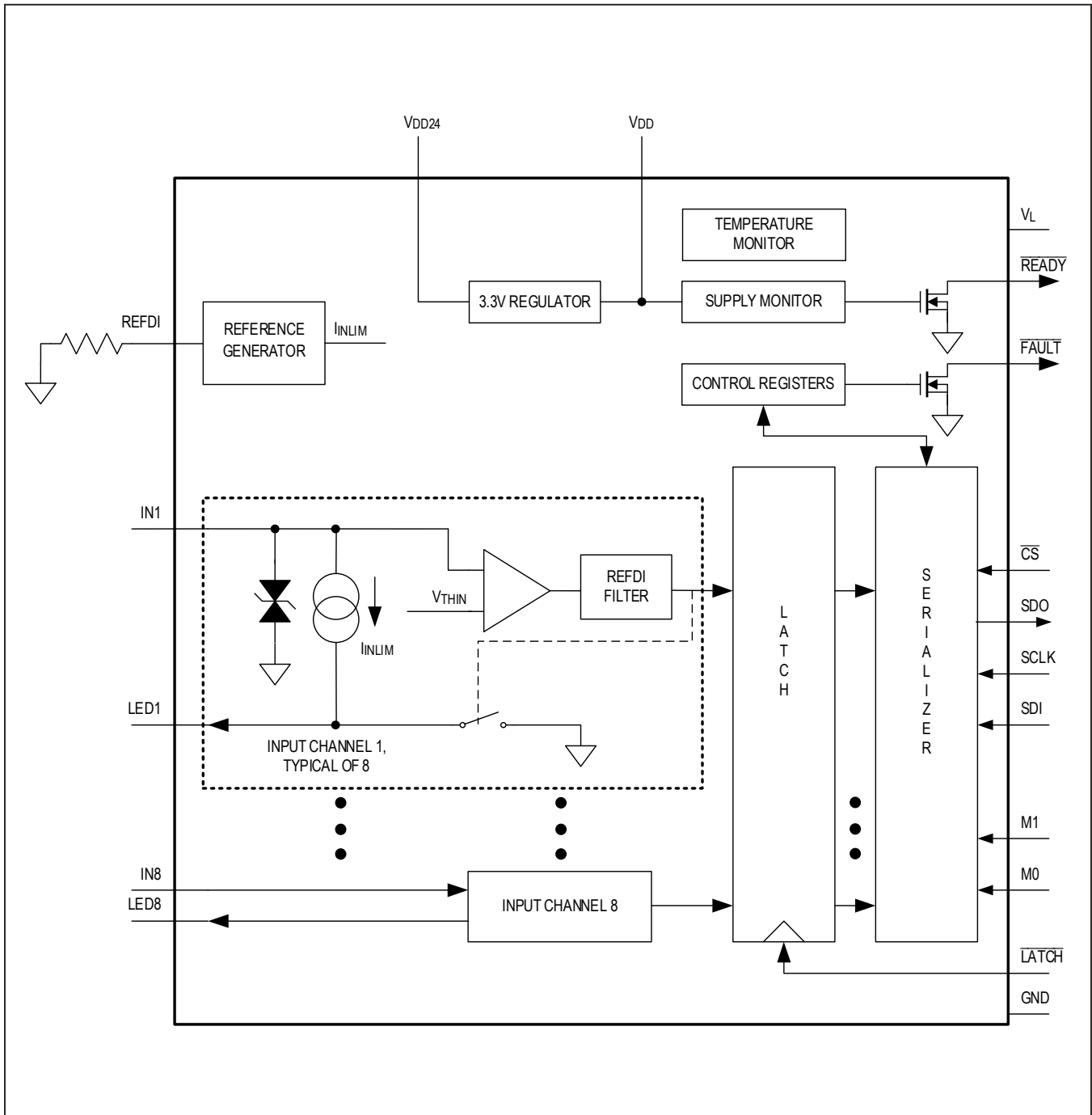
**Pin Configuration**



## Pin Description

| PIN                           | NAME                       | FUNCTION  |
|-------------------------------|----------------------------|---|
| <b>POWER SUPPLY</b>           |                            |   |
| 16                            | $V_L$                      | Logic Interface Supply, 3.0V to 5.5V. Bypass to GND with a 0.1 $\mu$ F capacitor in parallel with a 1 $\mu$ F capacitor.  |
| 25, 32                        | GND                        | Ground return for all field inputs and the field power supply.  |
| 30                            | $V_{DD24}$                 | 24V field supply. Bypass to GND with 0.1 $\mu$ F capacitor in parallel with 1 $\mu$ F capacitor.  |
| 31                            | $V_{DD}$                   | 3.3V Output from integrated LDO when powered from $V_{DD24}$ , or 3.0 – 5.5V Supply Input when $V_{DD24}$ not driven. Bypass to GND with 0.1 $\mu$ F capacitor in parallel with 1 $\mu$ F capacitor. If powering the MAX22199 from an external supply on $V_{DD}$ , leave $V_{DD24}$ unconnected.   |
| EP                            | —                          | Exposed Pad. Connect to GND. Solder entire exposed pad area to ground plane for best thermal performance.   |
| <b>SPI INTERFACE</b>          |                            |   |
| 9                             | $\overline{CS}$            | Chip-Select Input. Assert low to latch input states and enable the SPI interface.   |
| 10                            | SCLK                       | Serial Clock Input.   |
| 11                            | SDI                        | Serial Data Input. Data is clocked into SDI on the rising edge of SCLK.   |
| 12                            | $\overline{LATCH}$         | $\overline{LATCH}$ and $\overline{CS}$ control the data latching at the input of the serializer (after the inputs). The latch is transparent when both $\overline{CS}$ and $\overline{LATCH}$ are high. The data at the input of the serializer is frozen on the falling edge of either $\overline{LATCH}$ or $\overline{CS}$ . $\overline{LATCH}$ is typically used to synchronize input channel sampling across multiple MAX22199s. |
| 13                            | SDO                        | Serial Data Output. Data is updated on the falling edge of SCLK. When $\overline{CS}$ is high, SDO is high-impedance.   |
| 14                            | $\overline{FAULT}$         | Active-Low Fault Indicator. Open-drain output, $\overline{FAULT}$ goes low to indicate that one or more of the flags in the FAULT registers have been set. The faults include supply monitors, thermal shutdown, CRC error, etc.  |
| 15                            | $\overline{READY}$         | Open-Drain Output. $\overline{READY}$ goes low indicating that the MAX22199 is powered and ready for operation.   |
| <b>CONFIGURATION PINS</b>     |                            |   |
| 26                            | I.C.                       | Internally Connected. Leave I.C. unconnected or connect to GND.   |
| 27                            | REFDI                      | Digital Input Current-Limit Reference Resistor. For 24V Type 1 and Type 3 inputs, place a 7.5k $\Omega$ resistor from REFDI to GND.   |
| 28                            | M0                         | SPI Mode Control. Connect M1 to high to enable the SPI daisy-chain mode. Connect M0 to high to disable the CRC error detection. See <a href="#">Table 1</a> for details.  |
| 29                            | M1                         |   |
| <b>INPUT PINS</b>             |                            |   |
| 1, 3, 5, 7,<br>18, 20, 22, 24 | IN1–IN8,<br>respectively   | Field inputs. For Type 1 and Type 3 inputs, place a 1.5k $\Omega$ resistor between the field input and the IN_ pin. Capacitors for filtering should not be connected to the IN_ pins. See the <a href="#">Surge Protection of Field Inputs</a> section for further information.   |
| 2, 4, 6, 8,<br>17, 19, 21, 23 | LED1–LED8,<br>respectively | Energyless LED Driver Outputs. Connect to GND if LEDs are not used.   |

Functional Block Diagram



### Detailed Description

The MAX22199 senses the state (on, high or off, low) of eight digital inputs. The voltages at the IN1 to IN8 input pins are compared against internal references to determine whether the sensor is on (logic 1) or off (logic 0). All eight inputs are simultaneously latched by the assertion of either  $\overline{\text{LATCH}}$  or  $\overline{\text{CS}}$ , and the data is made available in a serialized format through the SPI interface. Placing a 7.5kΩ current-setting resistor between REFDI and GND, and a 1.5kΩ resistor between each field input and the corresponding IN\_ input pin ensures that the current at the ON and OFF trip points as well as the voltage at the trip points satisfy the requirements of IEC 61131-2 for Type

1 and Type 3 inputs. The current sunk by each input pin rises linearly with input voltage until the level set by the current limiter is reached; any voltage increase beyond this point does not increase the input current. Limiting the input current ensures compliance with IEC 61131-2 while significantly reducing power dissipation compared to traditional resistive inputs.

The current-setting resistor  $R_{\text{REFDI}}$  can be calculated using this equation:

$$R_{\text{REFDI}} = 17.63\text{V} \div I_{\text{INLIM}}$$

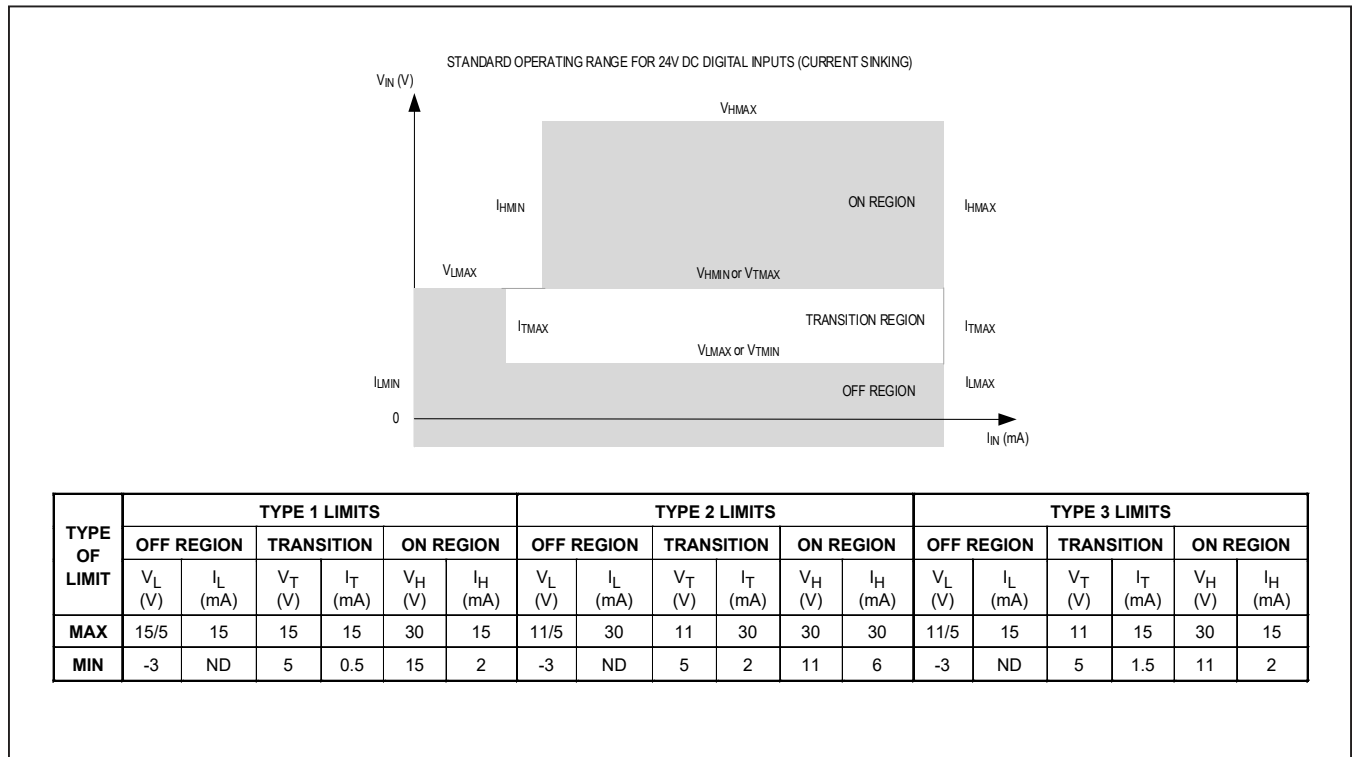


Figure 2. Switching Characteristics for IEC 61131-2 Type 1, 2, and 3 24VDC Digital Inputs

**Input Filters**

The MAX22199 features a digital filter per channel to reduce glitches and noise at the input, making an analog RC filter unnecessary. Capacitors should not be connected to the IN\_ pins for filtering. Each input (IN1 to IN8) has a programmable digital filter, input data can be filtered, or it can be bypassed for high-speed sampling. The input is sampled and data is latched at 1MHz (typ) when the input filter is disabled. When the digital filter is enabled, the input is sampled at 200kHz (typ). Bit FBP\_ in the corresponding FLT\_ register is used to bypass the filter or to enable the filter. One of eight filter delays (50µs, 100µs, 400µs, 800µs, 1.6ms, 3.2ms, 12.8ms, 20ms) can be independently selected for each channel.

Noise rejection is accomplished through a no-rollover up-down counter where the state of the field input controls the counting direction (up or down). The filter uses an up-down counter fed by a 200kHz clock. If the input is high, it counts up; if the input is low, it counts down. The

filter output is updated when the counter hits the upper or lower limit, with the upper limit depending on the selected filter delay and the lower limit being zero regardless of the filter delay. The low-to-high transition of the filter occurs when the counter reaches the upper limit. The high-to-low transition occurs when the counter reaches the lower limit. There is no rollover; counting simply stops when the upper or lower limit is hit. The filter delay is the time it takes to reach the upper/lower limit in response to a step input when the counter starts from the lower/upper limit. If the input is not a step function, but is bouncing, as shown in Figure 3, the output changes state after a total delay of:

$$\text{Total Delay} = \text{Filter Delay} + 2 \times (\text{Total Time at the Old State})$$

In the example in Figure 3, the filter has a nominal delay of 1.6ms, and the input returns high for two 0.2ms periods after the first transition from high to low. These transitions back to the high state extend the time before the output of the filter switches. Total Delay = 1.6ms + 2 x (0.2ms + 0.2ms) = 2.4ms.

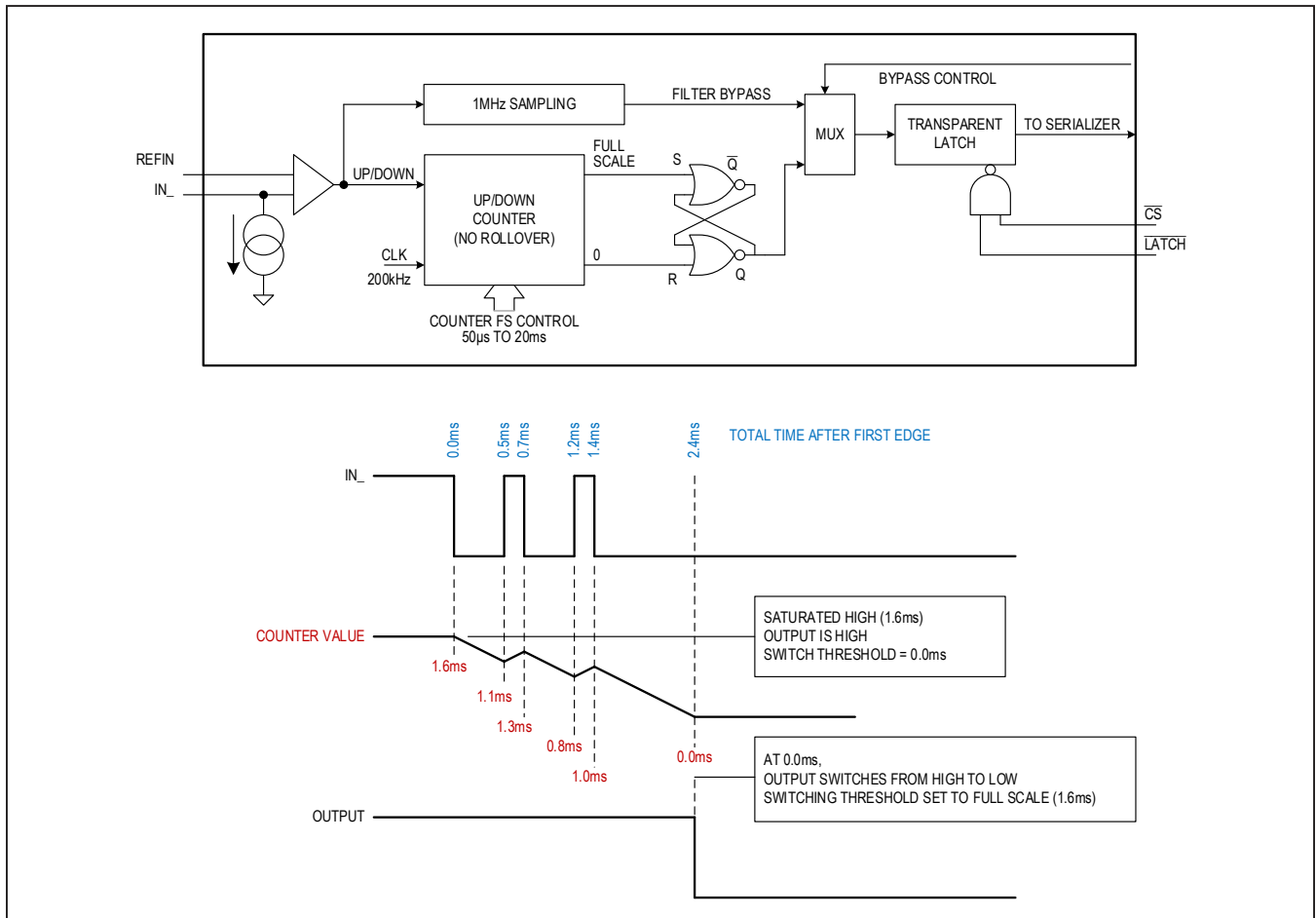


Figure 3. MAX22199 Digital Filter

**Energyless LED Drivers**

When IN<sub>n</sub> is determined to be on, its input current is diverted to the LED<sub>n</sub> pin and flows from that pin to GND. Placing an LED between LED<sub>n</sub> and GND provides an indication of the input state without increasing overall power dissipation. If the indicator LEDs are not used, connect LED<sub>n</sub> to GND.

**Type 2 Sensor Inputs**

The additional input current (6mA min) and associated power dissipation of Type 2 input requires the use of two MAX22199 inputs in parallel. The current of each channel is set to a nominal 3.39mA (6.78mA total) by placing a 5.2kΩ resistor from REFDI to GND. The proper voltage drop across the input resistor is maintained by reducing the resistance from 1.5kΩ to 1kΩ for each MAX22199 channel. For proper surge protection, it is important that each MAX22199 input has its own resistor. Any two MAX22199 channels can be used; they need not be contiguous (Figure 4). Either channel can be read to determine the input state. The additional power dissipa-

tion from this Type 2 configuration reduces the maximum ambient operating temperature to 120°C, when all inputs are at 30V, and the MAX22199 is powered from a 30V supply and there is no additional load on V<sub>DD</sub>.

**Thermal Consideration**

The MAX22199 operates at an ambient temperature of up to 125°C on a properly designed PCB. Operating at higher voltages, with heavy output loads on V<sub>DD</sub> while input channels are on increases power dissipation and reduces the maximum allowable operating temperature. See the [Package Information](#) and [Absolute Maximum Ratings](#) sections for safety operation temperature and maximum power dissipation.

The MAX22199 is in thermal shutdown when the thermal shutdown temperature threshold (165°C typical) is exceeded. During thermal shutdown, input channels, LED drivers, internal voltage regulator, and SPI interface are all turned off, except that register values are retained. A thermal shutdown event (OTSHDN) can be read back from the FAULT2 register once the device is out of thermal shutdown.

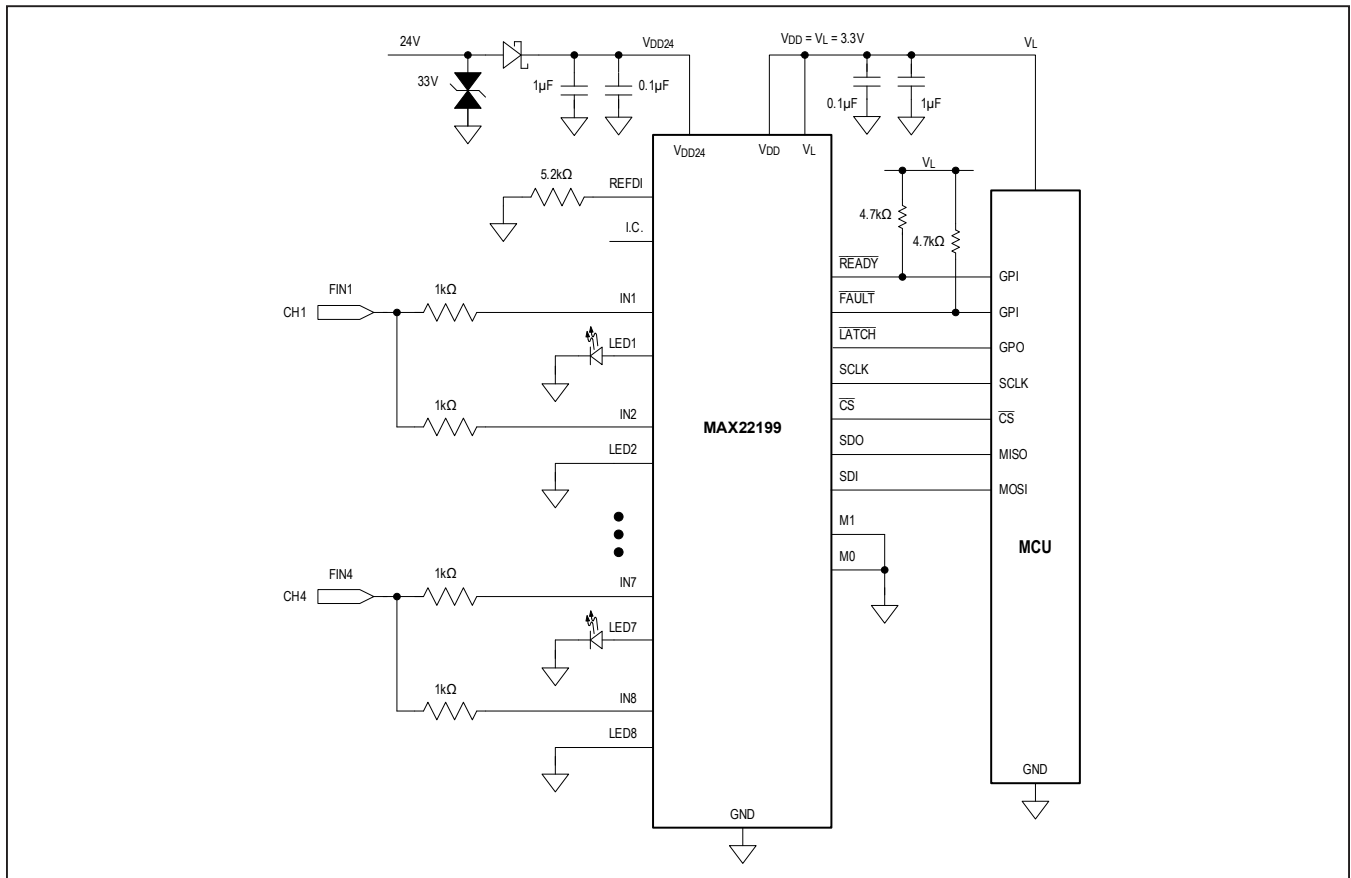


Figure 4. Implementing Type 2 Digital Inputs with the MAX22199



### Fault Detection and Monitoring

$\overline{\text{FAULT}}$  is an open-drain output that can be wire ORed with other open-drain outputs and used to notify the host processor of a fault. When enabled,  $\overline{\text{FAULT}}$  goes low to indicate that one or more of the flags in the FAULT1 register have been set. These faults are:  $V_{\text{DD}24}$  low voltage alarm (24VL),  $V_{\text{DD}24}$  voltage missing alarm (24VM), CRC error detected on the previous SPI frame (CRC), Power-On-Reset event (POR), and sources from the FAULT2 register.

Flags 24VL and 24VM in the FAULT1 register are latched; they remain set until read even if the fault goes away. The CRC bit is not latched, but remains set until an uncorrupted SPI frame is received. The POR bit indicates a power-on-reset event has happened, and is cleared only if the user writes a “0” to this bit. The FAULT2 bit is the logic OR result of the fault bits in the FAULT2 register, which include FAULT8CK and OTSHDN. The FAULT8CK bit is set when the number of clock pulses in a SPI frame is not equal to a multiple of eight. The OTSHDN bit indicates that the device had a thermal shutdown fault. The FAULT2 bit, and the FAULT8CK and OTSHDN bits are cleared-on-read.

Enable bits in the FAULT1EN and FAULT2EN registers select which flags in the FAULT1 and FAULT2 registers asserts the  $\overline{\text{FAULT}}$  pin. The enable bits do not affect the flags in the FAULT1 register, they only affect the  $\overline{\text{FAULT}}$  pin. [Figure 5](#) illustrates various register flags to assert the  $\overline{\text{FAULT}}$  pin.

The STK bit in the GPO register configures the  $\overline{\text{FAULT}}$  pin to be sticky or to clear when the fault is removed. For example: if a low voltage condition on  $V_{\text{DD}24}$  is detected, the 24VL bit in the FAULT1 register is set and  $\overline{\text{FAULT}}$  asserts low provided bit 24VLE in the FAULT1EN register is set. If  $V_{\text{DD}24}$  then returns to normal levels, the 24VL bit in the FAULT1 register remains set until read; however the state of the  $\overline{\text{FAULT}}$  pin depends on the configuration bit STK. If  $\text{STK} = 0$ , the  $\overline{\text{FAULT}}$  pin is not sticky and clears when the fault goes away even though the 24VL bit remains set. If  $\text{STK} = 1$ , then the  $\overline{\text{FAULT}}$  pin reflects the state of the bit in the FAULT1 register and remains set until the bit is cleared by reading the FAULT1 register. The minimum pulse width for  $\overline{\text{FAULT}}$  pin asserting low is 1 $\mu\text{s}$  (typical). This ensures adequate time for the assertion of  $\overline{\text{FAULT}}$  to be recognized by the host even if the fault was present for a shorter time.

The power-on default for the FAULT1EN register is to enable CRC and POR. The  $\overline{\text{FAULT}}$  pin is in the non-sticky mode.

### Clearing Bits in FAULT1 Register

The 24VL and 24VM sticky (or latched) bits in the FAULT1 register can be read and cleared either through a direct read of the FAULT1 register, or through a SPI Mode 0 or Mode 2 read or write command. If bit 24VF in the CFG register is equal to 0, SPI Mode 0 and 2 transactions read and clear bits 24VL and 24VM ([Table 3](#)). This valid SPI transaction also clears the CRC bit. Note that the CRC bit is only active in Mode 0 and 2 ( $\text{M}0 = 0$ ) since this is the only time a CRC test is performed. The POR bit is only cleared when the user writes a “0” to it.

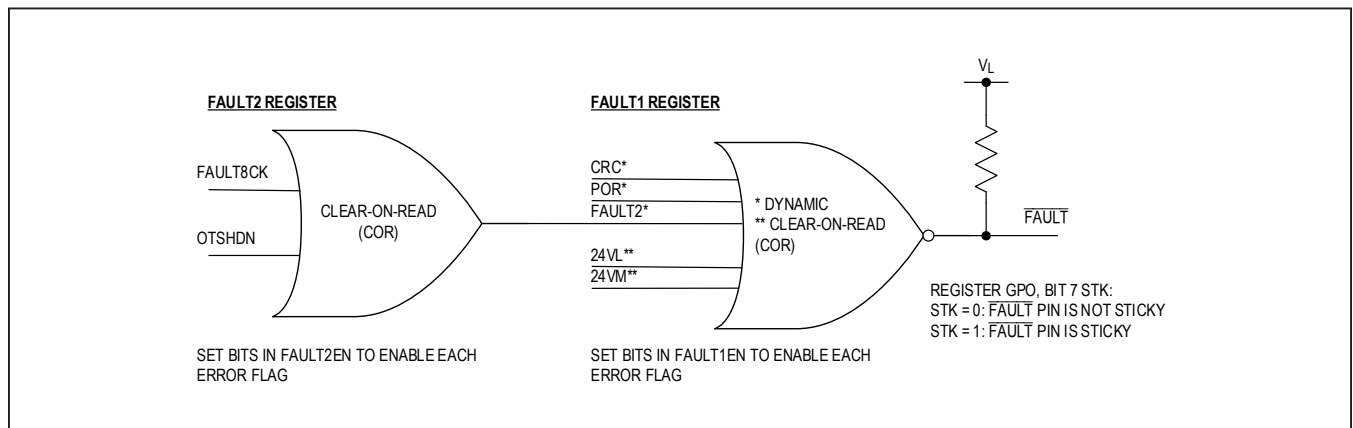


Figure 5.  $\overline{\text{FAULT}}$  Output Sources

**CRC Generation**

In the SPI interface Mode 0 and 2, five CRC bits can be used to check the data integrity during transfers between the device and an external microcontroller. In applications where the integrity of data transferred is not of concern, the CRC bits can be disabled by operating in the SPI Mode 1 and 3 (M0 = 1). The CRC uses the following polynomial:

$$P(x) = x^5 + x^4 + x^2 + x^0$$

The 5-bit CRC value is calculated using the first 19 data bits padded with the 5-bit initial word 00111. The 5-bit CRC result is then appended to the original data bits to create the 24-bit SPI data frame. When the MAX22199 receives a data frame with a CRC error, the CRC error flag (CRC) in the FAULT1 register is set and, if CRCE is set, the FAULT pin is asserted. The CRC bit is not sticky, but does remain set until an error-free frame is received. SPI commands within a corrupted frame are ignored. Refer to [AN6798](#) for CRC algorithm programming example.

**SPI Interface**

The MAX22199 has an SPI compatible interface used to read input data, read diagnostic data, and configure all of the registers. Each configuration register can be read back to ensure proper configuration. The SPI interface supports direct mode or daisy-chain mode by setting M1 pin to low or high. The CRC error detection can be

enabled or disabled by connecting M0 pin to GND or V<sub>L</sub> ([Table 1](#)). Asserting  $\overline{CS}$  low latches the state of all inputs and enables the SPI interface. For all modes, data at the SDI input is sampled on the rising edge of SCLK and data at SDO is updated on the falling edge of SCLK. The READ/WRITE bit is always the first bit of the SPI frame. Transitions of SCLK while  $\overline{CS}$  is deasserted (high) are ignored. SCLK must idle low when  $\overline{CS}$  is asserted.

**SPI Protocol**

The serial output of the device adheres to the SPI protocol, running with CPHA = 0 and CPOL = 0, as shown in [Figure 6](#). In all modes, the first 8 bits clocked out of SDO after  $\overline{CS}$  is asserted are data bits showing the status of inputs IN8–IN1; this allows for rapid and convenient retrieval of the primary data. For write operations in Mode 0 and 1, the next 8 bits clocked out of SDO are zero. For reads in Mode 0 and 1, the second 8 bits are the data from the specified register.

**Table 1. SPI Interface Modes**

| MODE | M1: M0 | FRAME LENGTH | CRC | DAISY CHAIN |
|------|--------|--------------|-----|-------------|
| 0    | 0 0    | 24-bit       | Yes | No          |
| 1    | 0 1    | 16-bit       | No  | No          |
| 2    | 1 0    | 24-bit       | Yes | Yes         |
| 3    | 1 1    | 16-bit       | No  | Yes         |

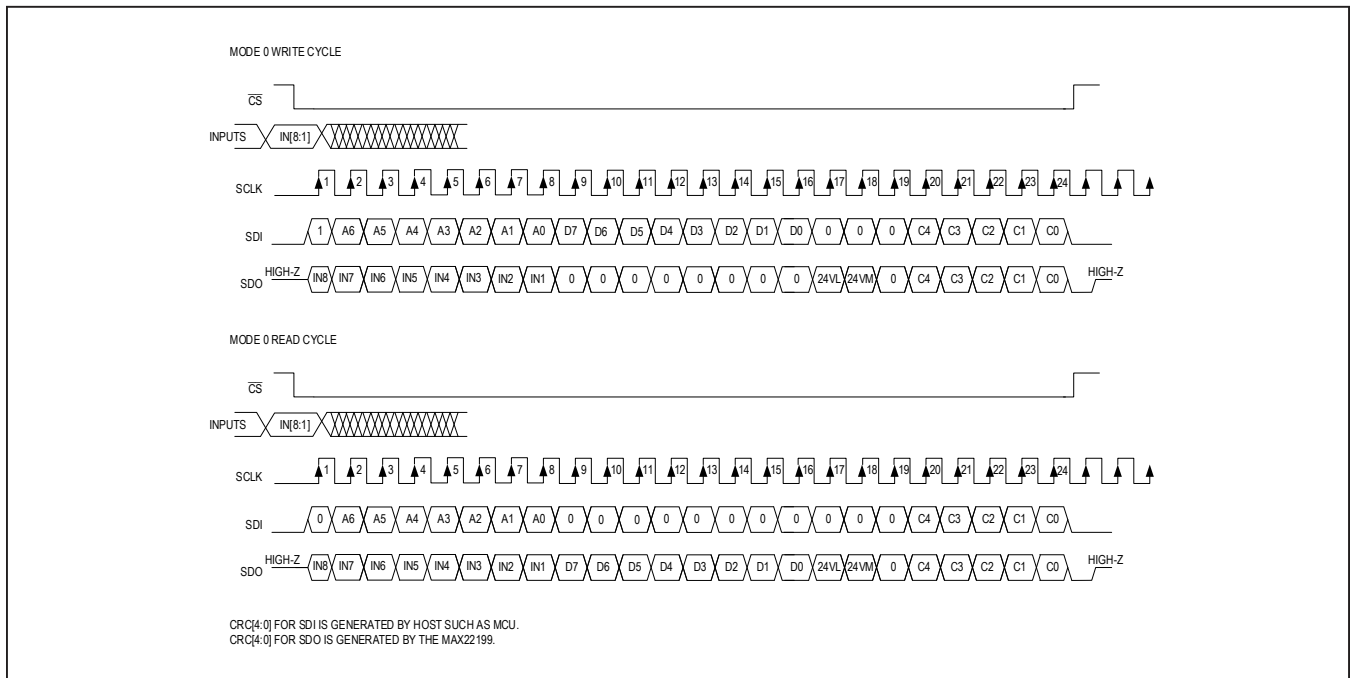


Figure 6. SPI Communication Example—Mode 0 Write and Read

Modes 2 and 3 are more complex, since the content of the second byte is determined by the previous instruction. For non-daisy-chain compatible modes (Mode 0 and 1), the read instruction is decoded on-the-fly as the SPI frame is clocked in. The instruction is immediately executed and data from the specified register is clocked out in the same SPI frame. This is convenient and quick, but not compatible with daisy-chaining. When daisy-chaining, each unit does not know which portion of the bit stream it should decode until  $\overline{CS}$  is deasserted (the frame is finished). To accommodate this, all daisy-chainable read instructions require two SPI frames. The first frame contains the read instruction and register address, and the second frame returns the register data as the second byte of the frame. This is true regardless of the instruction being clocked in during the second frame. See [Table 3](#) for detailed Mode 2 and 3 SPI commands.

$\overline{LATCH}$  is used to simultaneously capture the input states of different MAX22199s that are not controlled by the same  $\overline{CS}$ . This could be multiple MAX22199s in the same digital input module, or MAX22199s in different modules.

**Clock Count for Multiples of 8**

For each SPI cycle (between  $\overline{CS}$  going low and going high), the device counts the number of SCLK pulses. If it is not a multiple of 8, the SPI input data is discarded and bit FAULT8CK is set in the FAULT2 register.

**Table 2. SPI Port Power Status**

| V <sub>DD24</sub> | V <sub>DD</sub> | V <sub>L</sub> | SPI REGISTER MAP CONFIGURATION          | SPI PORT COMMUNICATION                 |
|-------------------|-----------------|----------------|---|--|
| Valid             | Valid           | Valid          | Configuration and fault data maintained | Normal Operation                       |
| Not Valid         | Valid           | Valid          | Configuration and fault data maintained | Normal Operation                       |
| Valid             | Not Valid       | X              | Configuration and fault data maintained | $\overline{CS}$ ignored, SDO is High-Z |
| X                 | Valid           | Not Valid      | Configuration and fault data maintained | $\overline{CS}$ ignored, SDO is High-Z |
| Not Valid         | Not Valid       | X              | Configuration and fault data lost       | $\overline{CS}$ ignored, SDO is High-Z |

**Note:** X = Don't Care

**SPI Power Status**

Only the SPI port buffers are powered from the V<sub>L</sub> supply; internal SPI circuits are powered from the V<sub>DD</sub> supply. Both V<sub>DD</sub> and V<sub>L</sub> must be valid for SPI communication to take place. In addition to powering the SPI circuits, V<sub>DD</sub> also sustains the SPI memory (configuration and status registers). If power is being supplied through V<sub>DD24</sub>, then an auxiliary supply for the memory is also available. The auxiliary supply only sustains memory, it does not allow SPI communication. The auxiliary supply takes over if V<sub>DD</sub> is lost due to external loading or due to a thermal shutdown event. When the event is over, the device configuration is maintained and fault information is available in the FAULT registers. See [Table 2](#) for the power requirement for SPI communication and register map configuration.

**Daisy-Chain Modes**

For systems with more than eight sensor inputs, multiple devices can be daisy-chained to allow access to all data inputs through a single serial port. When using a daisy-chain configuration, connect MOSI to SDI of the first device in the chain. Connect MISO to SDO of the last device in the chain. For all middle links, connect SDI to SDO of the previous device and SDO to SDI of the next device.  $\overline{CS}$  and SCLK of all devices in the chain should be connected together in parallel, see [Figure 7](#) which illustrates a 16-input application with daisy-chain connection and [Figure 8](#), which shows SPI timing in the daisy-chain mode.

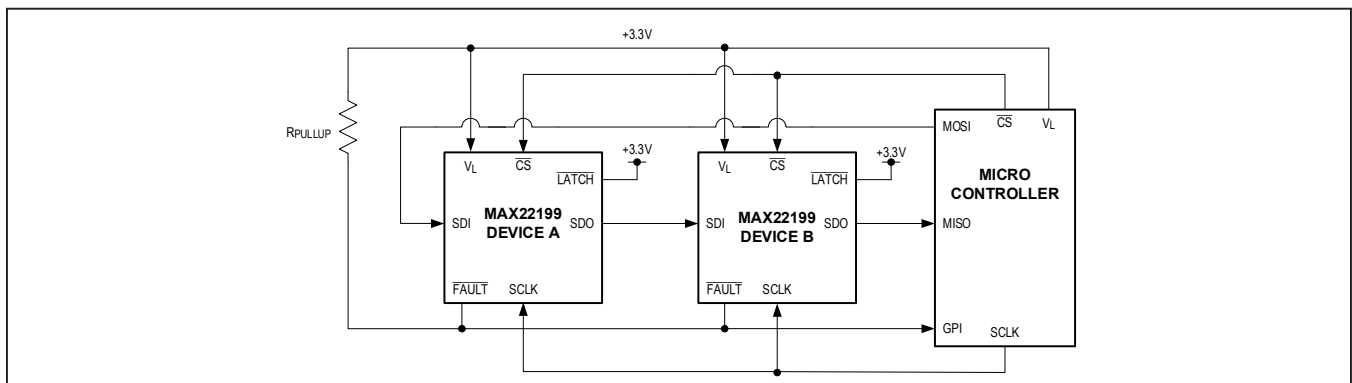


Figure 7. SPI Daisy-Chain Connection

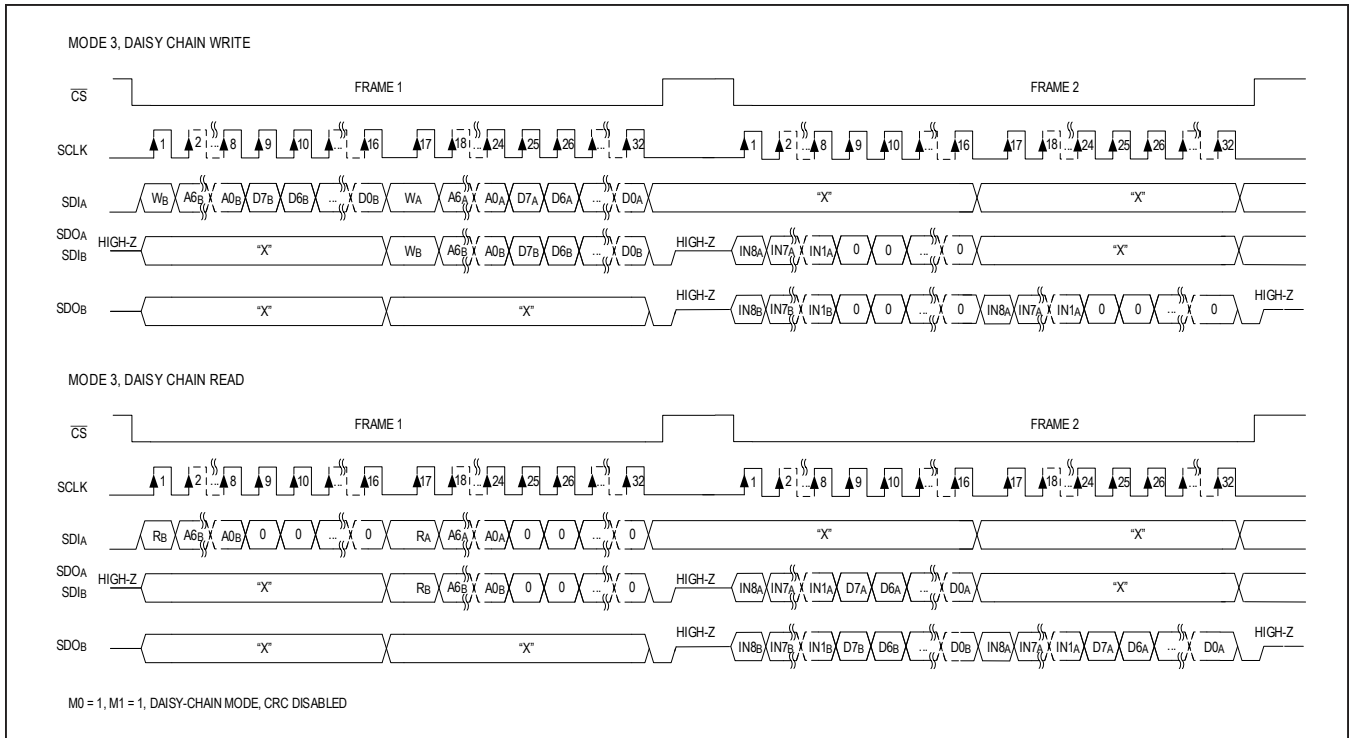


Figure 8. SPI Daisy-Chain Communication Example—Mode 3 Write and Read

### Configuration Flowchart

The MAX22199 powers on with default register settings and can be used in the default mode to read the data inputs, or it can be configured to match the individual application requirements. Before any register access for configuration or reading data, the MCU needs to wait until  $\overline{\text{READY}}$  goes low indicating that the MAX22199 is powered up and ready for use. Next, the MCU needs to clear the  $\overline{\text{FAULT}}$  pin that asserts low after every power-up event due to the default state (high) of the POR flag.

**Default Mode (Power-up mode):** In this mode, all input channel filters (FLT\_ registers) are set to bypass mode, all input channels are enabled, and all fault sources are disabled on  $\overline{\text{FAULT}}$  pin except the CRC and POR flags. Upon power-up, the POR flag is set to 1. If the  $\overline{\text{FAULT}}$  pin is being used, then a write operation must be performed to the FAULT1 register to reset POR to 0 for normal operating conditions. Now the MAX22199 can be polled to read data from DI register to show the logic state of the 8 input channels.

**Configurable Mode:** The MAX22199 can be configured for different parameters based upon the application requirements. The MCU can write to the various registers to set the options for input channel filters, enabling different fault sources on the  $\overline{\text{FAULT}}$  pin, or disabling specific input channels. In addition, the user can enable features such as making  $\overline{\text{FAULT}}$  pin sticky or not. Once the configuration is complete, the MAX22199 can be polled to read from DI register to show the logic state of the 8 input channels. Figure 9 demonstrates an example to configure the MAX22199.

**FAULT Asserted:** The MAX22199 uses the open-drain  $\overline{\text{FAULT}}$  pin to indicate to the MCU that a fault has occurred, often by using this pin to trigger an interrupt function within the MCU. The MCU can determine the source of the fault by reading register FAULT1. If bit 5 of FAULT1 is set, then register FAULT2 is indicating a fault and the FAULT2 register must also be read. Reading the FAULT\_ register clears the fault flag unless the fault condition persists, which immediately resets the flag.

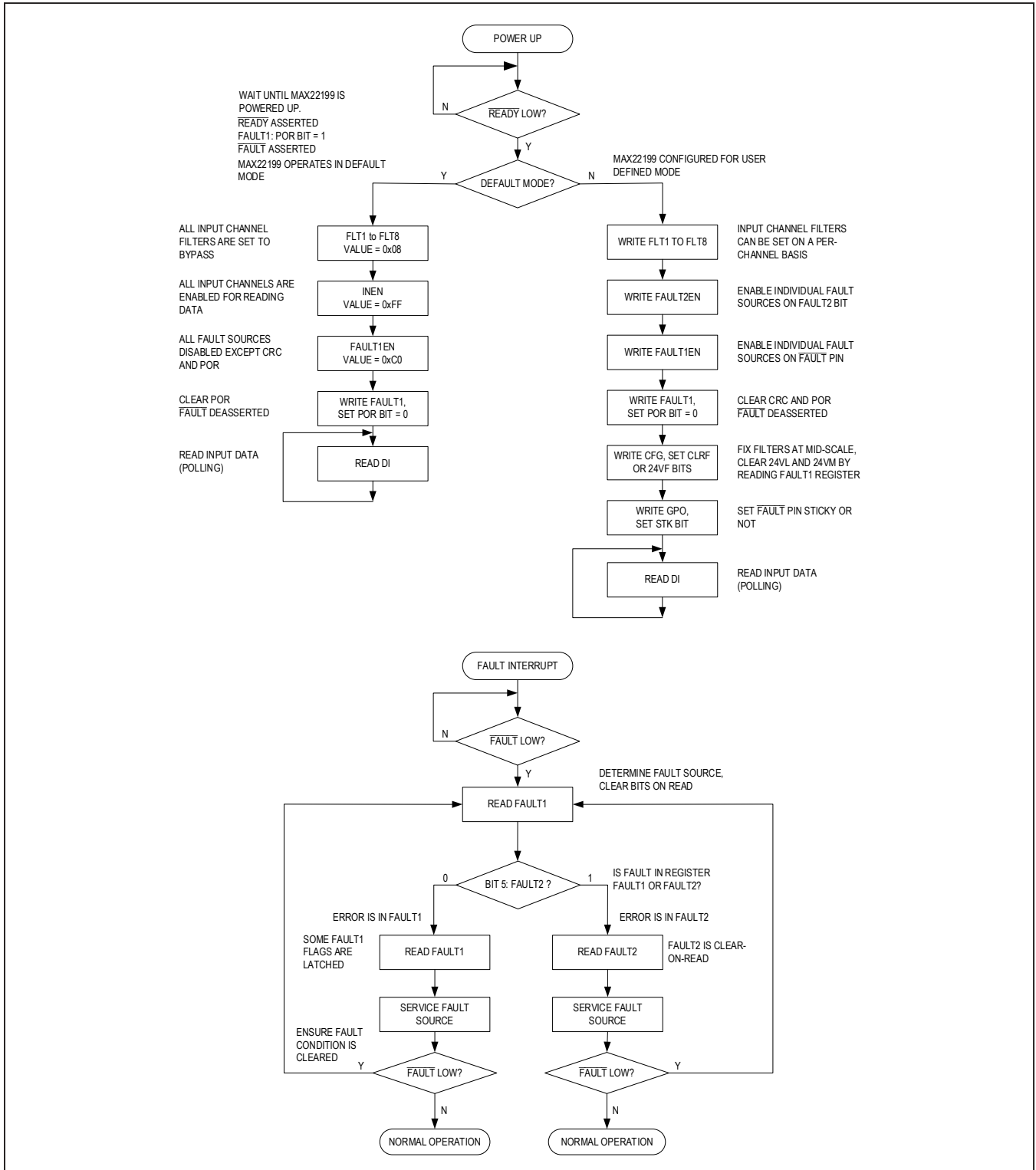


Figure 9. MAX22199 Configuration Flowchart

**Table 3. SPI Frames for SPI Modes**

**Mode 0: M1 = 0, M0 = 0 (CRC Enabled, SPI Direct Mode)**

Write

|            |                               |                            |                              |                         |      |   |                             |
|------------|-------------------------------|----------------------------|------------------------------|-------------------------|------|---|-----------------------------|
| <b>SDI</b> | MSB = 1<br>1 bit              | Register Address<br>7 bits | Write Data<br>8 bits         | 000 Fill Data<br>3 bits |      |   | CRC from Host<br>5 bits     |
| <b>SDO</b> | Input data: IN8–IN1<br>8 bits |                            | 00000000 Fill Data<br>8 bits | 24VL                    | 24VM | 0 | CRC from MAX22199<br>5 bits |

Read

|            |                               |                            |                                |                         |      |   |                             |
|------------|-------------------------------|----------------------------|--------------------------------|-------------------------|------|---|-----------------------------|
| <b>SDI</b> | MSB = 0<br>1 bit              | Register Address<br>7 bits | 00000000 Fill Data<br>8 bits   | 000 Fill Data<br>3 bits |      |   | CRC from Host<br>5 bits     |
| <b>SDO</b> | Input data: IN8–IN1<br>8 bits |                            | Register Data: D7–D0<br>8 bits | 24VL                    | 24VM | 0 | CRC from MAX22199<br>5 bits |

**Mode 1: M1 = 0, M0 = 1 (CRC Disabled, SPI Direct Mode)**

Write

|            |                               |                            |                              |
|------------|-------------------------------|----------------------------|------------------------------|
| <b>SDI</b> | MSB = 1<br>1 bit              | Register Address<br>7 bits | Write Data<br>8 bits         |
| <b>SDO</b> | Input data: IN8–IN1<br>8 bits |                            | 00000000 Fill Data<br>8 bits |

Read

|            |                               |                            |                                |
|------------|-------------------------------|----------------------------|--------------------------------|
| <b>SDI</b> | MSB = 0<br>1 bit              | Register Address<br>7 bits | 00000000 Fill Data<br>8 bits   |
| <b>SDO</b> | Input data: IN8–IN1<br>8 bits |                            | Register Data: D7–D0<br>8 bits |

**Mode 2: M1 = 1, M0 = 0 (CRC Enabled, Daisy-Chain Mode)**

Write – Preceding frame was a write or no-op

|            |                               |                            |                              |                         |      |   |                             |
|------------|-------------------------------|----------------------------|------------------------------|-------------------------|------|---|-----------------------------|
| <b>SDI</b> | MSB = 1<br>1 bit              | Register Address<br>7 bits | Write Data<br>8 bits         | 000 Fill Data<br>3 bits |      |   | CRC from Host<br>5 bits     |
| <b>SDO</b> | Input data: IN8–IN1<br>8 bits |                            | 00000000 Fill Data<br>8 bits | 24VL                    | 24VM | 0 | CRC from MAX22199<br>5 bits |

Write – Preceding frame was a read

|            |                               |                            |                                |                         |      |   |                             |
|------------|-------------------------------|----------------------------|--------------------------------|-------------------------|------|---|-----------------------------|
| <b>SDI</b> | MSB = 1<br>1 bit              | Register Address<br>7 bits | Write Data<br>8 bits           | 000 Fill Data<br>3 bits |      |   | CRC from Host<br>5 bits     |
| <b>SDO</b> | Input data: IN8–IN1<br>8 bits |                            | Register Data: D7–D0<br>8 bits | 24VL                    | 24VM | 0 | CRC from MAX22199<br>5 bits |

Read – Preceding frame was a write or no-op

|            |                               |                            |                              |                         |      |   |                             |
|------------|-------------------------------|----------------------------|------------------------------|-------------------------|------|---|-----------------------------|
| <b>SDI</b> | MSB = 0<br>1 bit              | Register Address<br>7 bits | 00000000 Fill Data<br>8 bits | 000 Fill Data<br>3 bits |      |   | CRC from Host<br>5 bits     |
| <b>SDO</b> | Input data: IN8–IN1<br>8 bits |                            | 00000000 Fill Data<br>8 bits | 24VL                    | 24VM | 0 | CRC from MAX22199<br>5 bits |

**Table 3: SPI Frames for SPI Modes (continued)**

Read – Preceding frame was a read

|            |                               |                            |                                |                         |      |   |                             |
|------------|-------------------------------|----------------------------|--------------------------------|-------------------------|------|---|-----------------------------|
| <b>SDI</b> | MSB = 0<br>1 bit              | Register Address<br>7 bits | 00000000 Fill Data<br>8 bits   | 000 Fill Data<br>3 bits |      |   | CRC from Host<br>5 bits     |
| <b>SDO</b> | Input data: IN8–IN1<br>8 bits |                            | Register Data: D7–D0<br>8 bits | 24VL                    | 24VM | 0 | CRC from MAX22199<br>5 bits |

**Mode 3: M1 = 1, M0 = 1 (CRC Disabled, Daisy-Chain Mode)**

Write – Preceding frame was a write or no-op

|            |                               |                            |                              |
|------------|-------------------------------|----------------------------|------------------------------|
| <b>SDI</b> | MSB = 1<br>1 bit              | Register Address<br>7 bits | Write Data<br>8 bits         |
| <b>SDO</b> | Input data: IN8–IN1<br>8 bits |                            | 00000000 Fill Data<br>8 bits |

Write – Preceding frame was a read

|            |                               |                            |                                |
|------------|-------------------------------|----------------------------|--------------------------------|
| <b>SDI</b> | MSB = 1<br>1 bit              | Register Address<br>7 bits | Write Data<br>8 bits           |
| <b>SDO</b> | Input data: IN8–IN1<br>8 bits |                            | Register Data: D7–D0<br>8 bits |

Read – Preceding frame was a write or no-op

|            |                               |                            |                              |
|------------|-------------------------------|----------------------------|------------------------------|
| <b>SDI</b> | MSB = 0<br>1 bit              | Register Address<br>7 bits | 00000000 Fill Data<br>8 bits |
| <b>SDO</b> | Input data: IN8–IN1<br>8 bits |                            | 00000000 Fill Data<br>8 bits |

Read – Preceding frame was a read

|            |                               |                            |                                |
|------------|-------------------------------|----------------------------|--------------------------------|
| <b>SDI</b> | MSB = 0<br>1 bit              | Register Address<br>7 bits | 00000000 Fill Data<br>8 bits   |
| <b>SDO</b> | Input data: IN8–IN1<br>8 bits |                            | Register Data: D7–D0<br>8 bits |

**Notes:**

SDI – CRC generated by external device such as MCU; data D7–D0 clocked out from MCU

SDO – CRC generated by the MAX22199; data D7–D0 clocked out from the MAX22199 register

NO-OP – No Operation, i.e. write cycle with no valid data to specified address

Write Cycle – DI8–DI1 are from internal latches, whose outputs are frozen when  $\overline{CS}$  or  $\overline{LATCH}$  goes low. Bits 24VL and 24VM are frozen by  $\overline{CS}$  going low but not by  $\overline{LATCH}$ .

Read Cycle – D7–D0 are the register data addressed through SDI. Bits 24VL and 24VM reflect the corresponding bits in the FAULT1 register.

In mode 1 and mode 3,  $\overline{CS}$  can be deasserted after eight clock cycles to retrieve the input data in a single-byte SPI command. The read or write command is ignored in this case.

**Table 4. Register Map**

| REGISTER        | ADDRESS | SYMBOL   | TYPE  | POR (DEFAULT) | 7   | 6    | 5         | 4       | 3    | 2     | 1           | 0   |
|-----------------|---------|----------|-------|---------------|---|------|-----------|---------|------|-------|-------------|-----|
| Digital Input   | 02h     | DI       | R     | 00h           | D18   | D17  | D16       | D15     | D14  | D13   | D12         | D11 |
| Fault 1         | 04h     | FAULT1   | MIXED | 46h           | CRC   | POR  | FAULT2    | 0       | 0    | 24VL  | 24VM        | 0   |
| Filter IN1      | 06h     | FLT1     | RW    | 08h           | 0   | 0    | 0         | X       | FBP1 |       | DELAY1[2:0] |     |
| Filter IN2      | 08h     | FLT2     | RW    | 08h           | 0   | 0    | 0         | X       | FBP2 |       | DELAY2[2:0] |     |
| Filter IN3      | 0Ah     | FLT3     | RW    | 08h           | 0   | 0    | 0         | X       | FBP3 |       | DELAY3[2:0] |     |
| Filter IN4      | 0Ch     | FLT4     | RW    | 08h           | 0   | 0    | 0         | X       | FBP4 |       | DELAY4[2:0] |     |
| Filter IN5      | 0Eh     | FLT5     | RW    | 08h           | 0   | 0    | 0         | X       | FBP5 |       | DELAY5[2:0] |     |
| Filter IN6      | 10h     | FLT6     | RW    | 08h           | 0   | 0    | 0         | X       | FBP6 |       | DELAY6[2:0] |     |
| Filter IN7      | 12h     | FLT7     | RW    | 08h           | 0   | 0    | 0         | X       | FBP7 |       | DELAY7[2:0] |     |
| Filter IN8      | 14h     | FLT8     | RW    | 08h           | 0   | 0    | 0         | X       | FBP8 |       | DELAY8[2:0] |     |
| Configuration   | 18h     | CFG      | RW    | 00h           | 0   | 0    | 0         | 24VF    | CLRF | 0     | 0           | X   |
| Input Enable    | 1Ah     | INEN     | RW    | FFh           | EN8   | EN7  | EN6       | EN5     | EN4  | EN3   | EN2         | EN1 |
| Fault 2         | 1Ch     | FAULT2   | COR   | 00h           | 0   | 0    | FAULT8CK  | OTSHDN  | 0    | 0     | 0           | 0   |
| Fault 2 Enables | 1Eh     | FAULT2EN | RW    | 00h           | 0   | 0    | FAULT8CKE | OTSHDNE | X    | X     | X           | X   |
| GPO             | 22h     | GPO      | RW    | 00h           | STK   | 0    | 0         | 0       | 0    | 0     | 0           | 0   |
| Fault 1 Enables | 24h     | FAULT1EN | RW    | C0h           | CRCE  | PORE | FAULT2E   | X       | X    | 24VLE | 24VME       | X   |
| No-Op           | 26h     | NOP      | NA    | -             | Dummy register. Contents of register DI are clocked out normally during attempted SPI writes to this register. Useful for daisy-chain mode. |      |           |         |      |       |             |     |

**Register Type Legend:**

- R: Read only
- RW: Read and Write
- COR: Clear-On-Read
- MIXED: Some bits are Clear-On-Read type, others are cleared differently. See bit descriptions for details.
- X: Don't care. Can be written as 1 or 0.



## Register Detailed Description

### DI (Read)

Address = 0x02

Default = 0x00

| BIT | NAME      | DESCRIPTION  |
|-----|-----------|--|
| 7:0 | DI8 – DI1 | 0: Channel x is driven low<br>1: Channel x is driven high<br>Digital input state. DI_ is the state of the corresponding input pin. |

### FAULT1 (Mixed)

Address = 0x04

Default = 0x46

| BIT | NAME   | DESCRIPTION   |
|-----|--------|---|
| 7   | CRC    | 0: The last received SPI frame was not corrupted.<br>1: The last received SPI frame was corrupted.<br>It is not cleared upon read, but when an uncorrupted SPI frame is received.<br>CRC is only active in SPI interface Mode 0 and 2.  |
| 6   | POR    | 0: Normal operating conditions<br>1: POR event has reset the register map to its power-on-reset state<br>This bit is cleared only if the user writes “0” to it. Other bits in this register are unaffected by the write access.   |
| 5   | FAULT2 | 0: All enabled bits in the FAULT2 register are not set<br>1: An enabled bit in the FAULT2 register is set<br>This bit is cleared on read only if the FAULT2 register is cleared or the bit is disabled.   |
| 4:3 | 0      | Reserved  |
| 2   | 24VL*  | 0: 24V supply is normal (above the 24VL threshold)<br>1: 24V supply is low (below the 24VL threshold)<br>Cleared upon reading this register. If bit 4 in the CFG register (24VF) is 0, 24VL can also be cleared after any SPI transaction while operation in Mode 0 or 2.     |
| 1   | 24VM*  | 0: 24V supply is normal (above the 24VM threshold)<br>1: 24V supply is missing (below the 24VM threshold)<br>Cleared upon reading this register. If bit 4 in the CFG register (24VF) is 0, 24VM can also be cleared after any SPI transaction while operation in Mode 0 or 2. |
| 0   | 0      | Reserved  |

*\*These flags are latched and they remain set until read even if the fault goes away, and are not cleared if the fault condition is still present when the register is read.*

**FLT1 to FLT8 (Read/Write)**

Address = 0x06 – 0x14 (increments of 2)

Default = 0x08

| BIT | NAME            | DESCRIPTION  |
|-----|-----------------|--|
| 7:5 | 0               | Reserved   |
| 4   | X               | Don't care. Can be written as 1 or 0   |
| 3   | FBP_            | FBP1 to FBP8.<br>0: Programmable filter on IN_ is used<br>1: Programmable filter on IN_ is bypassed  |
| 2:0 | DELAY_<br>[2:0] | DELAY1 to DELAY8. Programmable filter values for IN_:<br>DELAY_[2:0] = 000 = 50µs<br>DELAY_[2:0] = 001 = 100µs<br>DELAY_[2:0] = 010 = 400µs<br>DELAY_[2:0] = 011 = 800µs<br>DELAY_[2:0] = 100 = 1.6ms<br>DELAY_[2:0] = 101 = 3.2ms<br>DELAY_[2:0] = 110 = 12.8ms<br>DELAY_[2:0] = 111 = 20ms |

**CFG (Read/Write)**

Address = 0x18

Default = 0x00

| BIT | NAME | DESCRIPTION   |
|-----|------|---|
| 7:5 | 0    | Reserved  |
| 4   | 24VF | 0: Flags 24VL and 24VM are cleared after any full frame SPI transaction or by reading the FAULT1 register<br>1: 24VL and 24VM are cleared only by reading the FAULT1 register<br>Only affects SPI Mode 0 and 2. |
| 3   | CLRF | 0: All input filters operate normally<br>1: All input filters are fixed at the mid-scale value for the chosen delay<br>The filters resume normal operation when CLRF is cleared.                                |
| 2:1 | 0    | Reserved  |
| 0   | X    | Don't care. Can be written as 1 or 0  |

**INEN (Read/Write)**

Address = 0x1A

Default = 0xFF

| BIT | NAME      | DESCRIPTION   |
|-----|-----------|---|
| 7:0 | EN8 – EN1 | 0: EN_ = 0, IN_ is disabled, the current source is set to 0mA, and the DI_ bit in the DI register is set to 0<br>1: EN_ = 1, IN_ is enabled |

**FAULT2 (Clear-On-Read)**

Address = 0x1C

Default = 0x00

| BIT | NAME     | DESCRIPTION   |
|-----|----------|---|
| 7:6 | 0        | Reserved  |
| 5   | FAULT8CK | 0: SPI receives a number of clock pulses equal to a multiple of eight, valid transaction<br>1: SPI receives a number of clock pulses not equal to a multiple of eight, the SPI command is rejected  |
| 4   | OTSHDN   | 0: Normal operating conditions<br>1: Overtemperature shutdown (the safe operating temperature 165°C typical has been exceeded)<br>Overtemperature Shutdown: all inputs and LED drivers are turned off to reduce power dissipation and protect the device. The SPI interface and internal regulator remain active and if the temperature continues to rise, the regulator is turned off. |
| 3:0 | 0        | Reserved  |

**FAULT2EN (Read/Write)**

Address = 0x1E

Default = 0x00

| BIT | NAME      | DESCRIPTION   |
|-----|-----------|---|
| 7:6 | 0         | Reserved  |
| 5   | FAULT8CKE | 0: Disable bit FAULT2 in FAULT1 register<br>1: Enable bit FAULT2 in FAULT1 register to be set when FAULT8CK is high |
| 4   | OTSHDNE   | 0: Disable bit FAULT2 in FAULT1 register<br>1: Enable bit FAULT2 in FAULT1 register to be set when OTSHDN is high   |
| 3:0 | X         | Don't care. Can be written as 1 or 0  |

**GPO (Read/Write)**

Address = 0x22

Default = 0x00

| BIT | NAME | DESCRIPTION   |
|-----|------|---|
| 7   | STK  | 0: $\overline{\text{FAULT}}$ pin is not sticky. $\overline{\text{FAULT}}$ condition is determined by the logical OR of the unmasked real-time FAULT1 register sources, and not the FAULT1 register bits.<br>1: $\overline{\text{FAULT}}$ pin is sticky. If at least one bit in the FAULT1 register is set and unmasked, $\overline{\text{FAULT}}$ pin remains low until FAULT1 register is read (Figure 5). |
| 6:0 | 0    | Reserved  |

**FAULT1EN (Read/Write)**

Address = 0x24

Default = 0xC0

| BIT | NAME    | DESCRIPTION  |
|-----|---------|--|
| 7   | CRCE    | 0: $\overline{\text{FAULT}}$ pin is not asserted when CRC is 1<br>1: $\overline{\text{FAULT}}$ pin is asserted when CRC is 1       |
| 6   | PORE    | 0: $\overline{\text{FAULT}}$ pin is not asserted when POR is 1<br>1: $\overline{\text{FAULT}}$ pin is asserted when POR is 1       |
| 5   | FAULT2E | 0: $\overline{\text{FAULT}}$ pin is not asserted when FAULT2 is 1<br>1: $\overline{\text{FAULT}}$ pin is asserted when FAULT2 is 1 |
| 4:3 | X       | Don't care. Can be written as 1 or 0   |
| 2   | 24VLE   | 0: $\overline{\text{FAULT}}$ pin is not asserted when 24VL is 1<br>1: $\overline{\text{FAULT}}$ pin is asserted when 24VL is 1     |
| 1   | 24VME   | 0: $\overline{\text{FAULT}}$ pin is not asserted when 24VM is 1<br>1: $\overline{\text{FAULT}}$ pin is asserted when 24VM is 1     |
| 0   | X       | Don't care. Can be written as 1 or 0   |

**NOP (N/A)**

Address = 0x26

Default = N/A

| BIT | NAME     | DESCRIPTION  |
|-----|----------|--|
| 7:0 | NOP[7:0] | Dummy register. D18–D11 bits are clocked out normally during attempted writes to this register. Useful for daisy-chain mode. |

## Applications Information

### Power Supply Sequencing

The MAX22199 does not require special power supply sequencing. The SPI interface logic level ( $V_L$ ) is set independently from the field supply ( $V_{DD24}$ ) or LDO output ( $V_{DD}$ ) levels.

### Power Supply Decoupling

To reduce ripple and the chance of introducing data errors, bypass  $V_{DD24}$ ,  $V_L$ , and  $V_{DD}$  with  $0.1\mu\text{F} \parallel 1\mu\text{F}$  ceramic capacitors to GND, respectively. Place the bypass capacitors as close as possible to the power supply input pins.

### Powering the MAX22199 With the $V_{DD}$ Pin

The MAX22199 can alternatively be powered using a 3.0–5.5V supply connected to the  $V_{DD}$  pin. In this case a 24V supply is no longer needed and the  $V_{DD24}$  pin must be left unconnected. This configuration has lower power consumption and heat dissipation since the on-chip LDO voltage regulator is disabled (the  $V_{DD24}$  undervoltage lockout is below threshold and automatically disables the LDO).

In this configuration, the device always indicates a 24V FAULT due to bits 24VL and 24VM in the FAULT1 register, and the FAULT pin is always active (low) if the bits are enabled in the FAULT1EN register. To overcome this, set bits 24VLE and 24VME in the FAULT1EN register to 0.

### PCB Layout Recommendations

The PCB designer should follow some critical recommendations in order to get the best performance from the design.

- Keep the input/output traces as short as possible. To keep signal paths low inductance, avoid using vias.

- Have a solid ground plane underneath the entire EP area with multiple thermal vias for best thermal performance.
- In order to achieve the optimal EFT performance, it is recommended to have the GND plane around the REFDI trace, and isolate the REFDI trace from all input traces as much as possible.

### Isolating the SPI Interface

A companion product, the MAX14483 is available, which is optimized to support the MAX22199. The MAX14483 is a 6-channel,  $3.75\text{kV}_{\text{RMS}}$ , low-power digital isolator ideal for interfacing to low-voltage products such as microcontrollers or FPGAs. [Figure 10](#) demonstrates daisy-chain operation, showing SPI signals, control signals, and power monitoring signals isolated between the field and logic side of the design. A single MAX14483 can be used for multiple MAX22199s.

[Figure 11](#) demonstrates two MAX22199s connected as independent slaves, meaning they have separate chip select ( $\overline{\text{CS}}$ ) signals from the master (MCU). The AUX channel of the MAX14483 can be used to isolate the second  $\overline{\text{CS}}$  signal. Care must be taken to ensure both MAX22199s are not enabled simultaneously to avoid SPI-bus contention.

In both [Figure 10](#) and [Figure 11](#), the  $\overline{\text{READY}}$  signal from both MAX22199 devices are connected together to the  $\overline{\text{IRDY}}$  pin of the MAX14483. The  $\overline{\text{IRDY}}$  is pulled low when one of the MAX22199 devices is ready for operation. Care must be taken with the software to determine if both of the MAX22199s are ready. Alternatively, an OR gate can be used between  $\overline{\text{READY}}$  signals to guarantee the  $\overline{\text{IRDY}}$  is only pulled low when both the  $\overline{\text{READY}}$  signals are low.

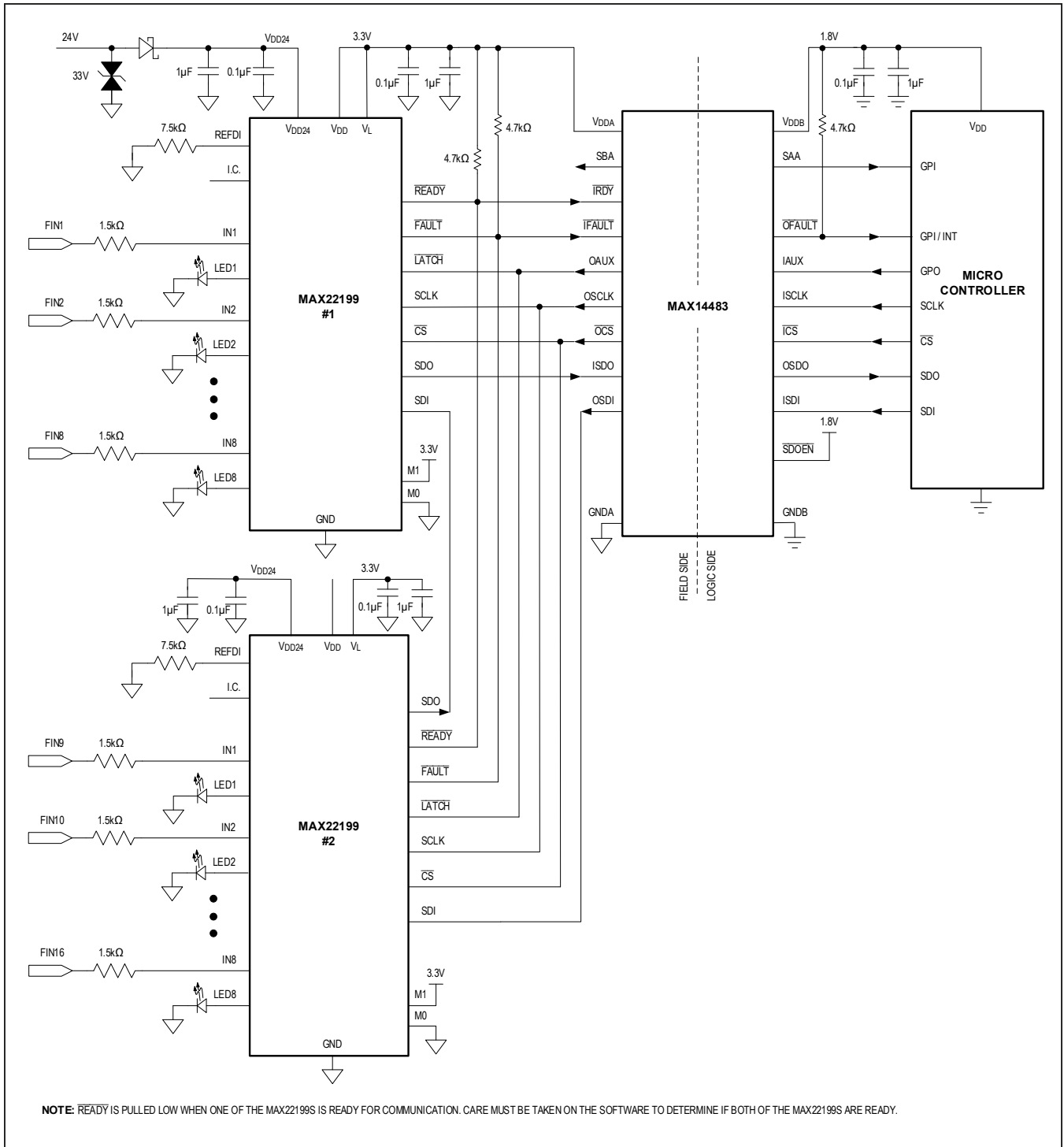


Figure 10. 16-Channel Type 1/3 Digital Input, SPI Daisy Chain

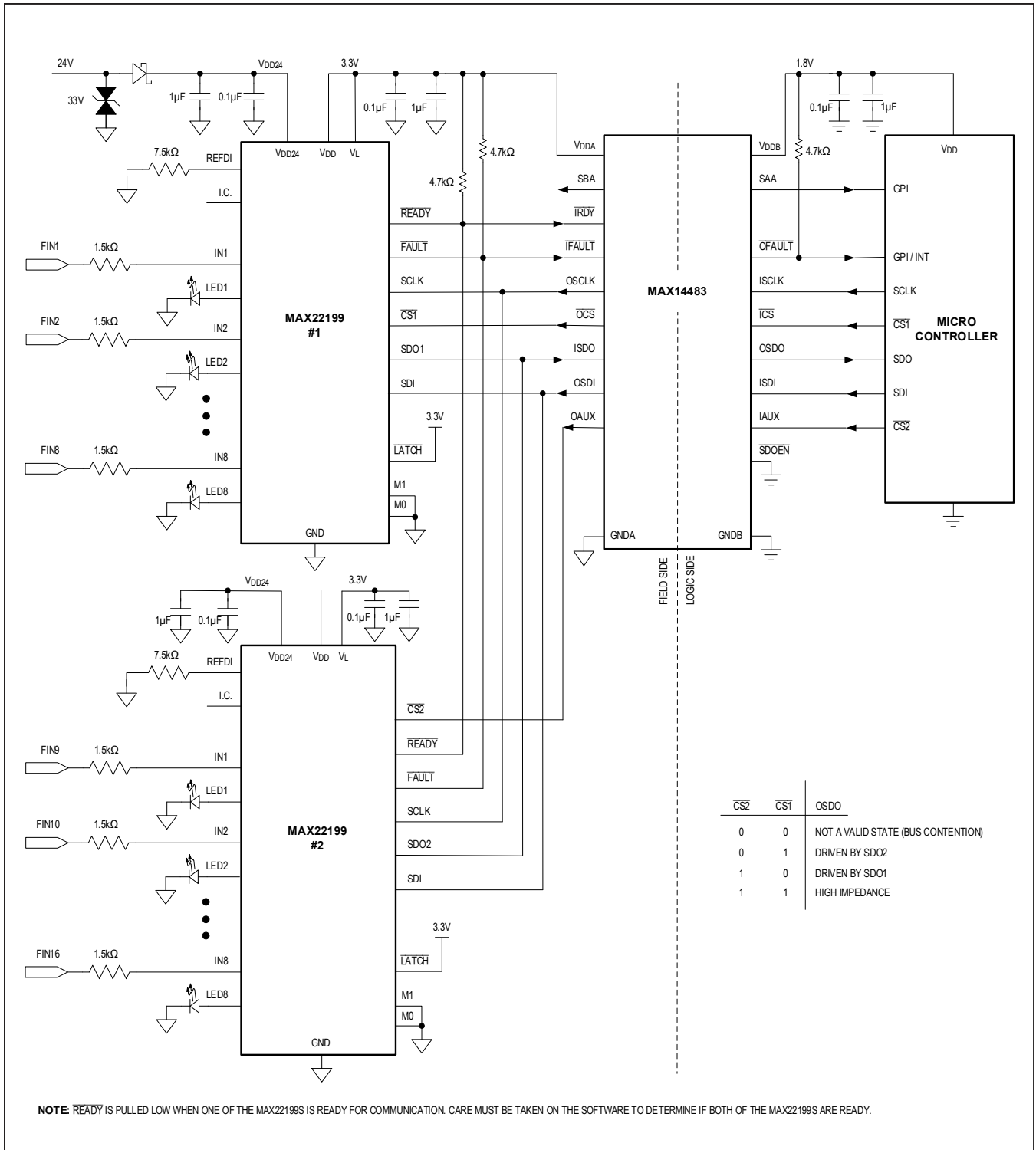


Figure 11. 16-Channel Type 1/3 Digital Input, Independent Slave SPI (Separate CS for Each SPI Slave)

**IEC 61131-2 EMC Requirement**

The MAX22199 is required to operate reliably in harsh industrial environments. The device can meet the transient immunity requirements as specified in IEC 61131-2, including Electrostatic Discharge (ESD) per IEC 61000-4-2, Electrical Fast Transient/Burst (EFT) per IEC 61000-4-4, and Surge Immunity per IEC 61000-4-5. Maxim’s proprietary process technology provides robust input channels and field supply with internal ESD structures and high Absolute Maximum Ratings (see the [Absolute Maximum Ratings](#) section), but external components are

also required to absorb excessive energy from ESD and surge transients. The circuit with external components shown in [Figure 12](#) allows the device to meet and exceed the transient immunity requirements as specified in IEC 61131-2 and related IEC 61000-4-x standards. The system shown in [Figure 12](#), using the components shown in [Table 5](#), is designed to be robust against ESD, EFT, and Surge specifications as listed in [Table 6](#). In all these tests, the part or DUT is soldered onto a properly designed application board (e.g., the MAX22199EVKIT#) with necessary external components.

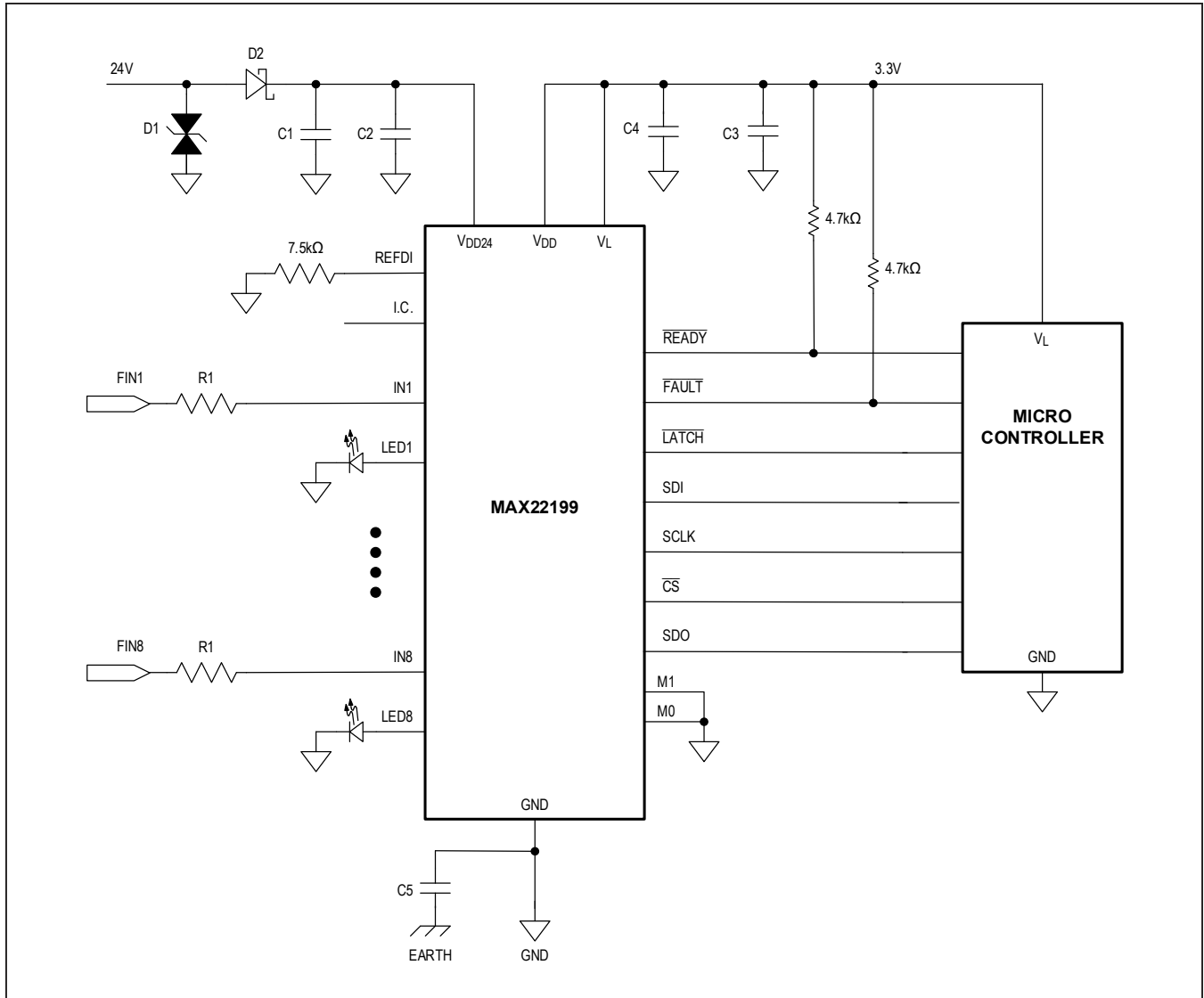


Figure 12. Typical EMC Protection Circuitry for the MAX22199



**Table 5. Recommended Components**

| COMPONENT           | DESCRIPTION  | REQUIRED/RECOMMENDED/OPTIONAL |
|---------------------|--|-------------------------------|
| C1                  | 1 $\mu$ F, 100V low ESR ceramic capacitor  | Required                      |
| C2                  | 0.1 $\mu$ F, 100V low ESR ceramic capacitor  | Required                      |
| C3                  | 1 $\mu$ F, 10V low ESR ceramic capacitor   | Required                      |
| C4                  | 0.1 $\mu$ F, 10V low ESR ceramic capacitor   | Required                      |
| C5                  | 3300pF safety rated Y capacitor (2220)   | Recommended                   |
| D1                  | Bidirectional TVS diode, SMAJ33CA (42 $\Omega$ ) or SM30T39CAY (2 $\Omega$ )                             | Recommended                   |
| D2                  | Schottky diode for reverse current protection  | Recommended                   |
| R1                  | 1.5k $\Omega$ or 1k $\Omega$ , 1W pulse withstanding resistor (CMB0207, RPC2512, CRCW2512-IF or similar) | Required                      |
| All other resistors | 0603, 0.1W resistors   | Required                      |
| All LEDs            | LED for visual input status indication   | Recommended                   |

### ESD Protection of Field Inputs

The input resistor limits the energy into the MAX22199 IN\_ pins and protects the internal ESD structure from excessive transient energy. An input series resistor is required and should be rated to withstand such ESD levels. The MAX22199 input channels can withstand up to  $\pm 8$ kV ESD contact discharge and  $\pm 15$ kV ESD air-gap discharge with an input series resistor of 1k $\Omega$  or larger. The input resistor value shifts the field voltage switching threshold scaled by the input current; thus, it determines the input characteristics of the application. The package of the resistor should be large enough to prevent the arcing across the two resistor pads. Arcing depends on the ESD level applied to the field input and the application's pollution degree.

### EFT Protection of Field Inputs

The input channels can withstand up to  $\pm 4$ kV, 5kHz or 100kHz fast transients (Figure 14) with performance criterion A, normal operation within specification limits. A capacitive coupling clamp is used to couple the fast transients (burst) from the EFT generator to the field inputs of the MAX22199 without any galvanic connection to the MAX22199 input pins.

### Surge Protection of Field Inputs

In order to protect the IN\_ pins against IEC 61000-4-5 surges (Figure 15 and Figure 16), two options exist.

The first option is to use a series pulse withstanding resistor as shown in the various application diagrams in the data sheet. A pulse resistor greater or equal to 1k $\Omega$  should be used to withstand  $\pm 2$ kV/42 $\Omega$ , 1.2/50 $\mu$ s surge pulses. The pulse resistor should support dissipation of the surge energy. Examples of suitable resistors are CMB0207 MELF, RPC2512 or CRCW2512-IF thick film as well as others. The required resistor value is defined by the Type 1, 2, 3, or other input characteristics. Capacitors for filtering should not be connected to the IN\_ pins.

The second option, which can result in a smaller overall footprint, is to use a bidirectional TVS to GND at the field input with a low-power series resistor, greater or equal to 1k $\Omega$  (Figure 17). The TVS must be able to absorb the surge energy and has the function of limiting the peak voltage so that the resistor only sees a low differential voltage. Suitable TVS include SMAJ33CA, SPT02-236 or PDFN3-32 which has a smaller footprint, offering protection against  $\pm 1$ kV/42 $\Omega$  surges.

### Surge Protection of 24V Supply

In order to protect the V<sub>DD24</sub> pin against 500V/42 $\Omega$ , 1.2/50 $\mu$ s surges (Figure 15), a SMAJ33CA TVS can be applied to the V<sub>DD24</sub> pin, along with a series Schottky diode for reverse current protection.

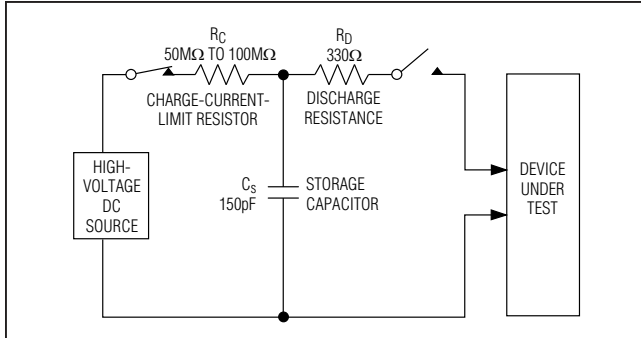


Figure 13a. ESD Test Circuit

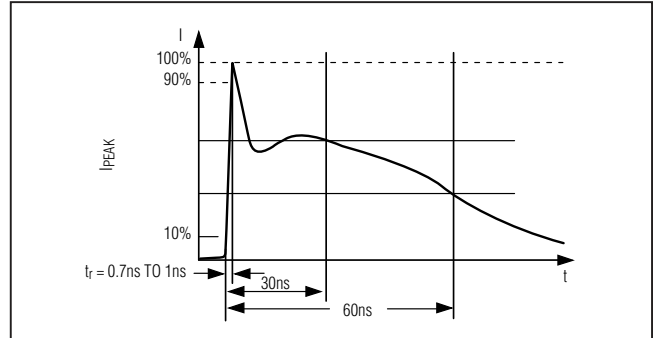


Figure 13b. ESD Contact Discharge Test Waveform

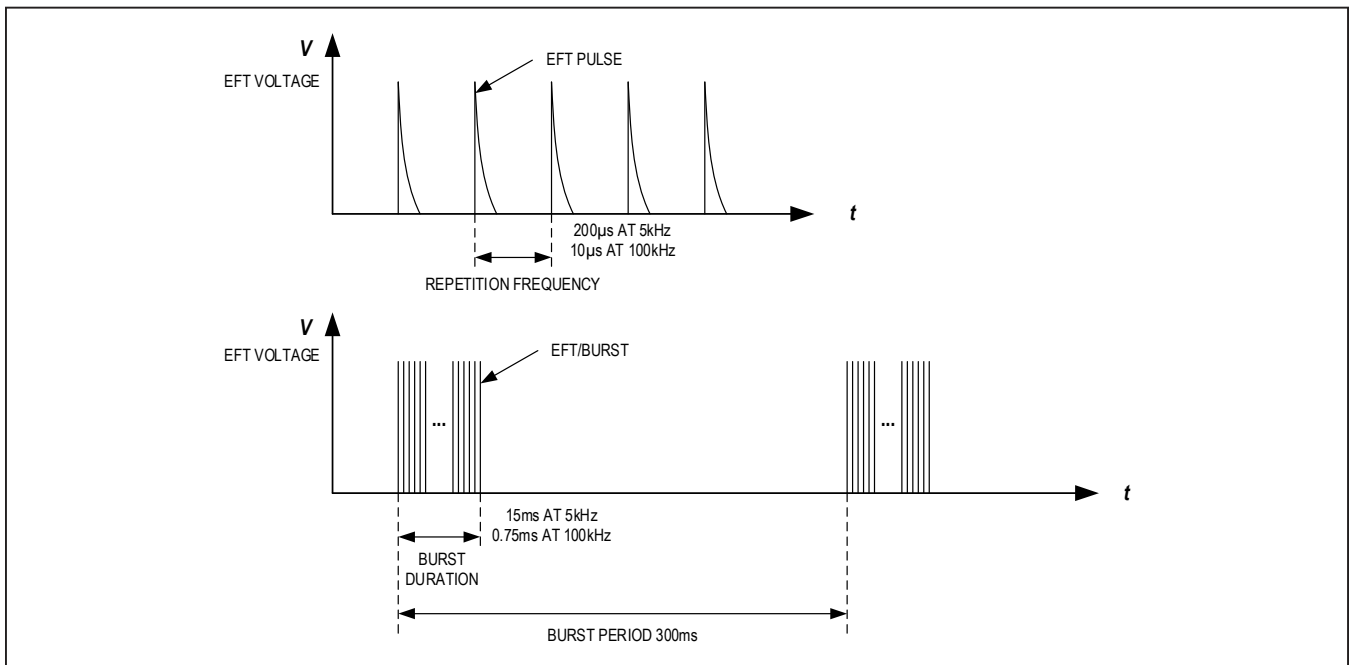


Figure 14. Electrical Fast Transient/Burst Waveform

**Table 6. Transient Immunity Test Results**

| TEST  |                | RESULT |
|---|----------------|--------|
| IEC 61000-4-2 Electrostatic Discharge (ESD)         | Contact ESD    | ±8kV   |
|   | Air-Gap ESD    | ±15kV  |
| IEC 61000-4-4 Electrical Fast Transient/Burst (EFT) | Input Line     | ±4kV   |
| IEC 61000-4-5 Surge Immunity (1.2/50µs, 42Ω)        | Line-to-Ground | ±2kV   |
|   | Line-to-Line   | ±2kV   |
|   | Power Supply   | ±500V  |

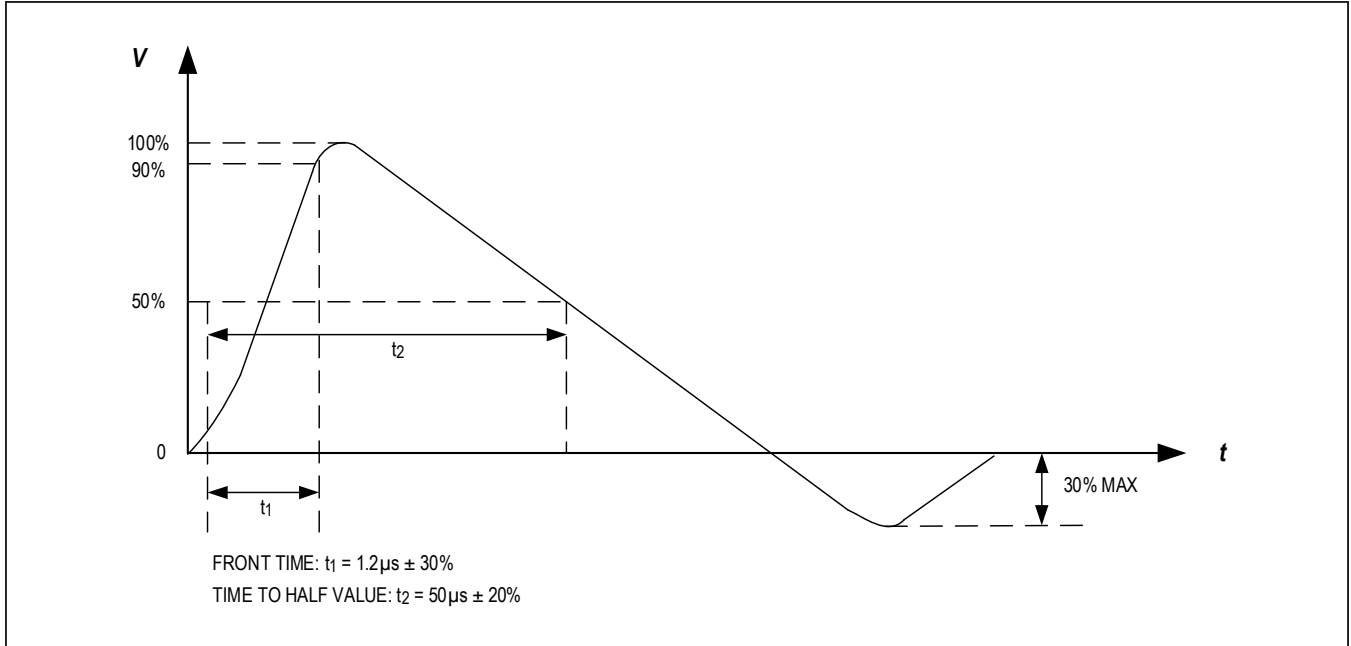


Figure 15. 1.2/50µs Surge Voltage Waveform

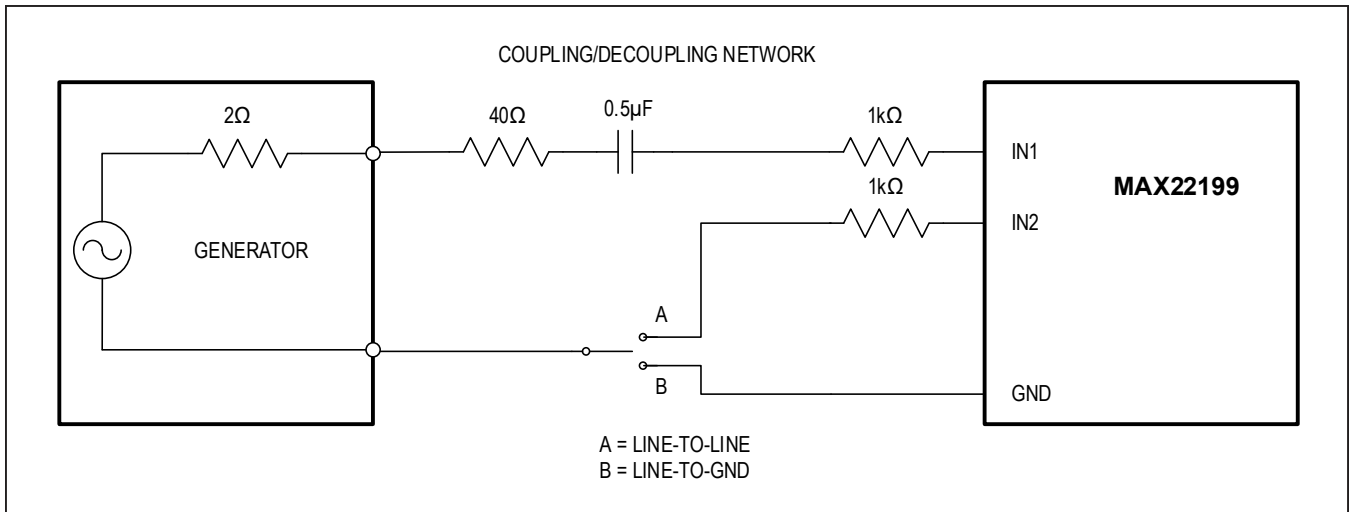


Figure 16. Surge Testing Methods

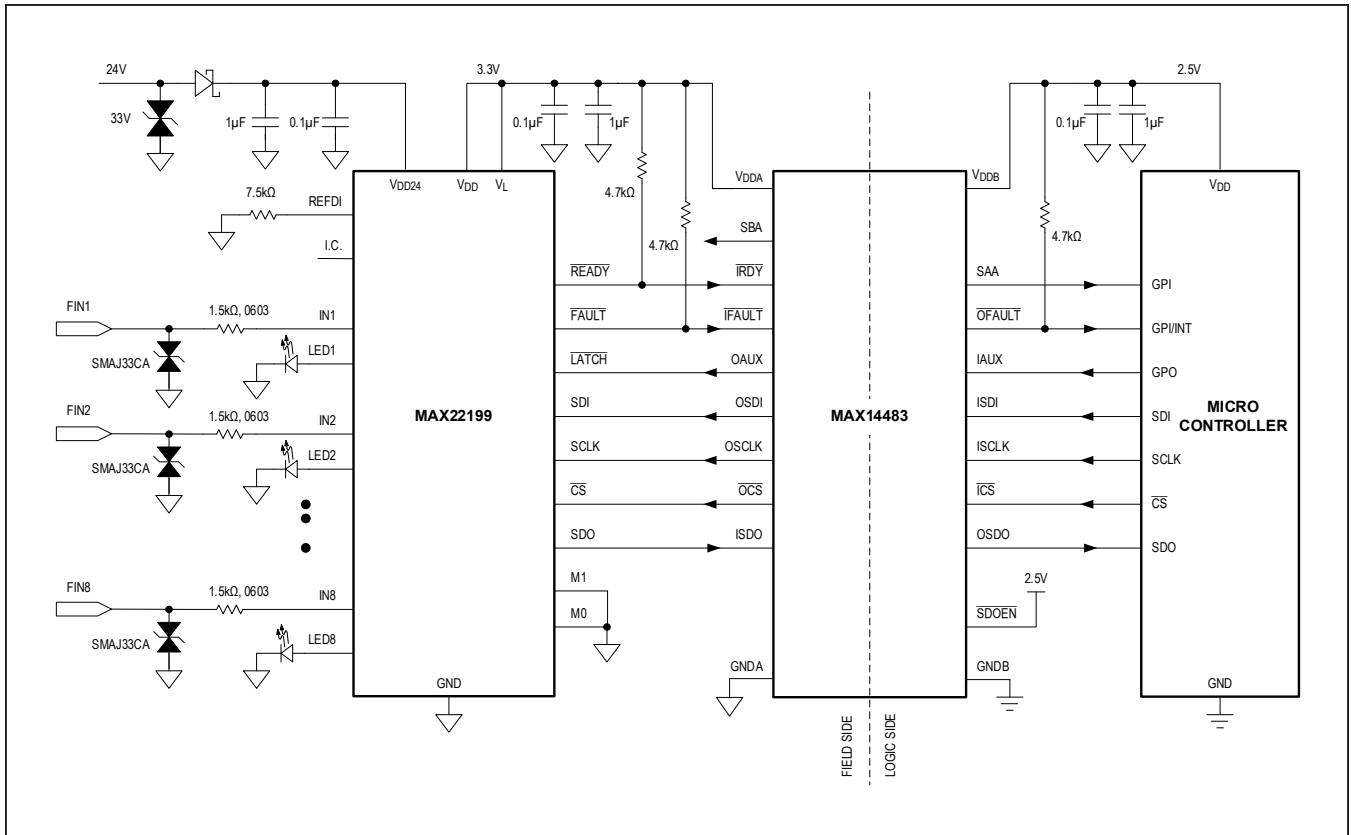


Figure 17. MAX22199 Input Surge Protection with TVS

### Ordering Information

| PART NUMBER   | TEMP RANGE      | PIN-PACKAGE |
|---------------|-----------------|-------------|
| MAX22199ATJ+  | -40°C to +125°C | 32-TQFN     |
| MAX22199ATJ+T | -40°C to +125°C | 32-TQFN     |

+Denotes a lead(Pb)-free/RoHS-compliant package.

T = Tape and reel.

### Chip Information

PROCESS: BiCMOS

## Revision History

| REVISION NUMBER | REVISION DATE | DESCRIPTION     | PAGES CHANGED |
|-----------------|---------------|-----------------|---------------|
| 0               | 5/21          | Initial release | —             |

For pricing, delivery, and ordering information, please visit Maxim Integrated's online storefront at <https://www.maximintegrated.com/en/storefront/storefront.html>.

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